

## Flash Memory Programming Specification

### 1.0 DEVICE OVERVIEW

This document includes the programming specifications for the following devices:

- PIC18F24K50
- PIC18F25K50
- PIC18F26K50
- PIC18F45K50
- PIC18F46K50
- PIC18LF24K50
- PIC18LF25K50
- PIC18LF26K50
- PIC18LF45K50
- PIC18LF46K50

### 2.0 PROGRAMMING OVERVIEW

The PIC18(L)F2X/4XK50 devices can be programmed using either the high-voltage In-Circuit Serial Programming™ (ICSP™) method or the low-voltage ICSP method. Both methods can be done with the device in the users' system. The low-voltage ICSP method is slightly different than the high-voltage method and these differences are noted where applicable. This programming specification applies to the PIC18(L)F2X/4XK50 devices in all package types.

#### 2.1 Hardware Requirements

In High-Voltage ICSP mode, the PIC18(L)F2X/4XK50 devices require two programmable power supplies: one for VDD and one for MCLR/VPP/RE3. Both supplies should have a minimum resolution of 0.25V. Refer to [Section 6.0 “AC/DC Characteristics Timing Requirements for Program/Verify Test Mode”](#) for additional information.

##### 2.1.1 LOW-VOLTAGE ICSP PROGRAMMING

In Low-Voltage ICSP mode, the PIC18(L)F2X/4XK50 devices can be programmed using a single VDD source in the operating range. The MCLR/VPP/RE3 does not have to be brought to a different voltage, but can instead be left at the normal operating voltage. Refer to [Section 2.7 “Entering and Exiting Low-Voltage ICSP Program/Verify Mode”](#) for additional hardware parameters.

**Note 1:** The High-Voltage ICSP mode is always available, regardless of the state of the LVP bit, by applying VIH to the MCLR/VPP/RE3 pin.

**2:** While in Low-Voltage ICSP mode, MCLR is always enabled, regardless of the MCLRE bit, and the RE3 pin can no longer be used as a general purpose input.

#### 2.2 Dedicated ICSP/ICD Port (44-Pin TQFP Only)

The PIC18F45K50/46K50 44-pin TQFP devices are designed to support an alternate programming input: the dedicated ICSP/ICD port. The primary purpose of this port is to provide an alternate In-Circuit Debugging (ICD) option and free the pins (RB6, RB7 and MCLR) that would normally be used for debugging the application. In conjunction with ICD capability, however, the dedicated ICSP/ICD port also provides an alternate port for ICSP. Setting the ICPRT Configuration bit enables the dedicated ICSP/ICD port. The dedicated ICSP/ICD port functions the same as the default ICSP/ICD port; however, alternate pins are used instead. Table 2-2 identifies the functionally equivalent pins for ICSP purposes: The dedicated ICSP/ICD port is an alternate port. Thus, ICSP is still available through the default port even though the ICPRT Configuration bit is set.

**Note:** The ICPRT Configuration bit can only be programmed through the default ICSP port. By default the ICPRT Configuration bit is enabled. When the ICPRT Configuration bit is cleared (dedicated ICSP/ICD port is disabled), the ICDPORTS pin should be tied to either VDD or VSS on 44 TQFP packages only. The ICPRT Configuration bit must be maintained clear for all 28-pin and 40-pin devices; otherwise, unexpected operation may occur.

# PIC18(L)F2X/4XK50

## 2.2.1 ICPRT DISABLED

Clearing the ICPRT bit in CONFIG4L disables the use of the dedicated port function and leaves the dedicated pins floating. High-voltage and low-voltage programming are performed using the MCLR/VPP, PGC and PGD pins as normal. This is otherwise known as the legacy interface mode, using the standard interface pins.

## 2.2.2 ICPRT ENABLED

Setting the ICPRT bit in CONFIG4L enables the use of the dedicated port function through the dedicated pins. This is the default setting for the ICPRT bit upon start-up or Reset. When using devices in packages other than the 44-pin TQFP, the ICPRT bit must be cleared.

The standard interface pins will remain operational, even after the dedicated pins are enabled, unless the user assigns another function to them in firmware. If another function is not assigned to the standard pins and both sets of pins remain operable for programming, whichever high-voltage entry pin (the standard VPP pin or the dedicated ICDVPP pin) is activated first will take priority.

For high-voltage programming, if high-voltage is detected on the ICDVPP pin first, the standard MCLR/VPP pin will be ignored and programming must be performed using the ICDPGC and ICDPGD pins. If high-voltage is detected on the MCLR/VPP pin first, the dedicated ICDVPP pin will be ignored and programming must be performed using the PGC and PGD pins. These same rules apply to the low-voltage programming sequence.

## 2.3 Pin Diagrams

The pin diagrams for the PIC18(L)F2X/4XK50 family are shown in Figures 2-1 through 2-4.

**TABLE 2-1: PIN DESCRIPTIONS (DURING PROGRAMMING): PIC18(L)F2X/4XK50**

Pin Name	During Programming		
	Pin	Pin Type	Pin Description
MCLR/VPP/RE3	VPP	P	Programming Enable
VDD <sup>(1)</sup>	VDD	P	Power Supply
VSS <sup>(1)</sup>	VSS	P	Ground
RB6	PGC	I	Serial Clock
RB7	PGD	I/O	Serial Data
ICDRST/ICDVPP <sup>(2)</sup>	VPP	P	Programming Enable
ICDCLK/ICDPGC	PGC	I	Serial Clock
ICDDAT/ICDPGD <sup>(2)</sup>	PGD	I/O	Serial Data

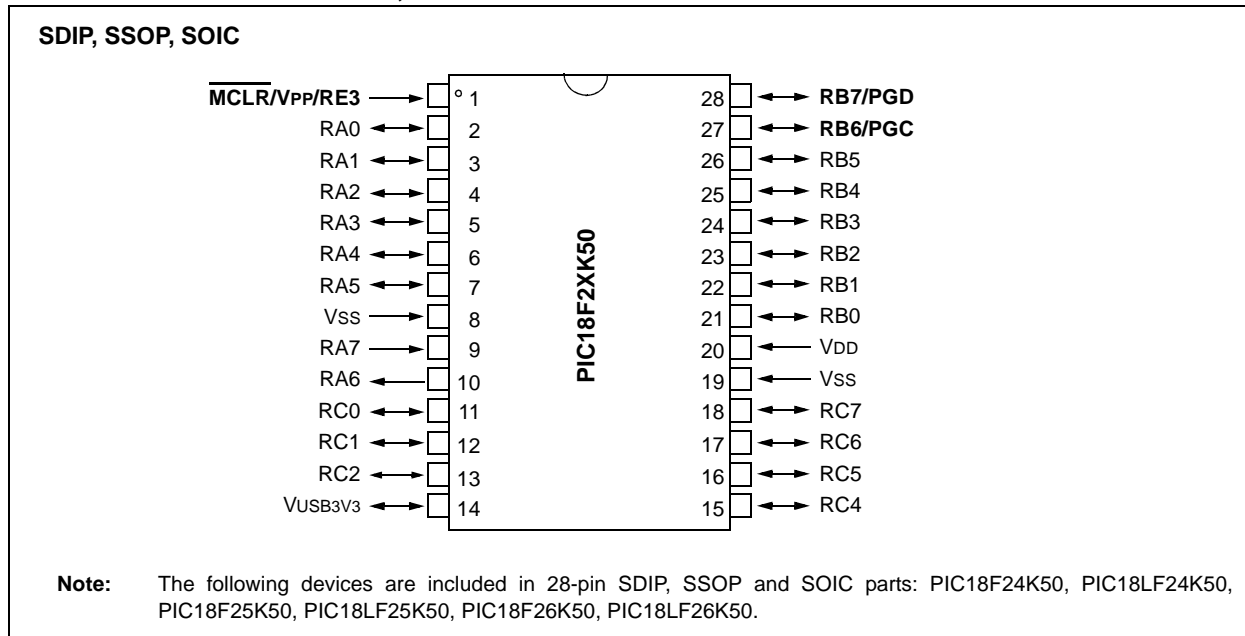
**Legend:** I = Input, O = Output, P = Power

**Note 1:** All power supply (VDD) and ground (VSS) pins must be connected.

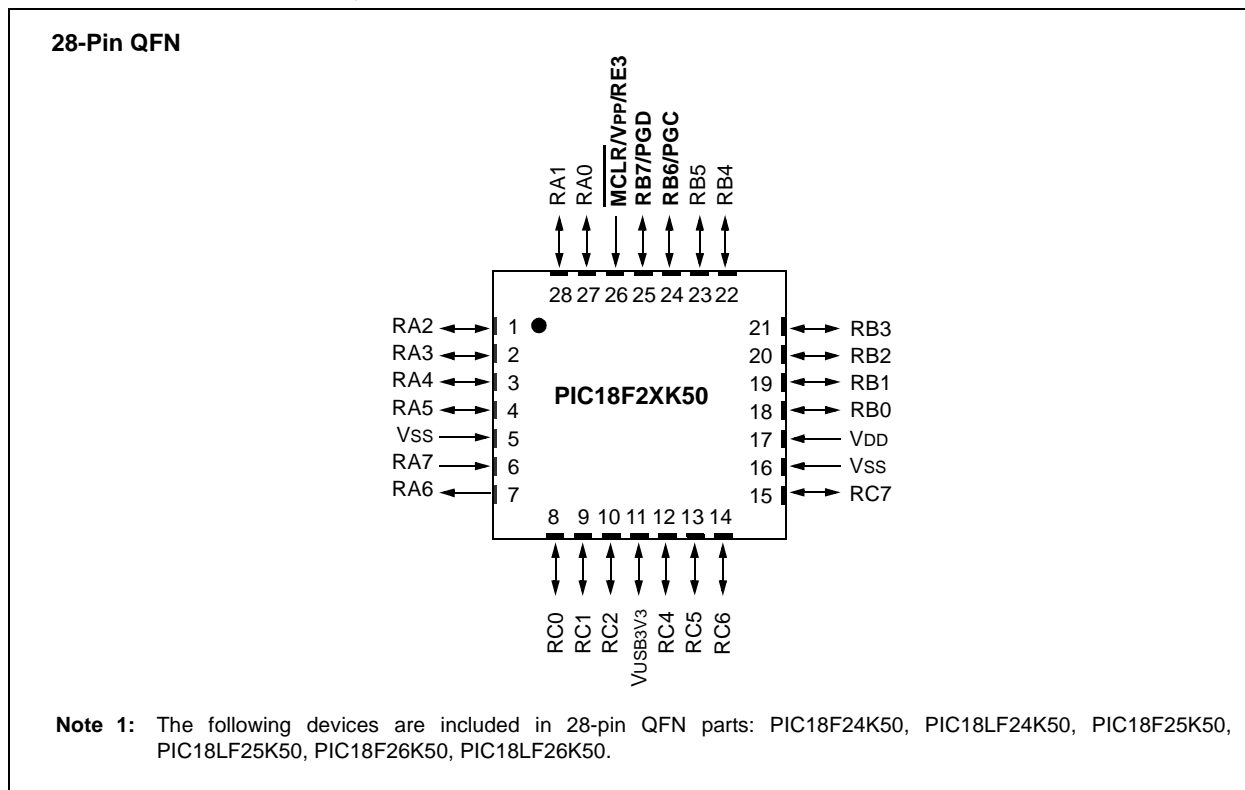
**Note 2:** Dedicated ICSP/ICD Port available on 44-pin TQFP only when the ICPRT bit in CONFIG4L is enabled.

# PIC18(L)F2X/4XK50

**FIGURE 2-1: 28-PIN SDIP, SSOP AND SOIC PIN DIAGRAMS**

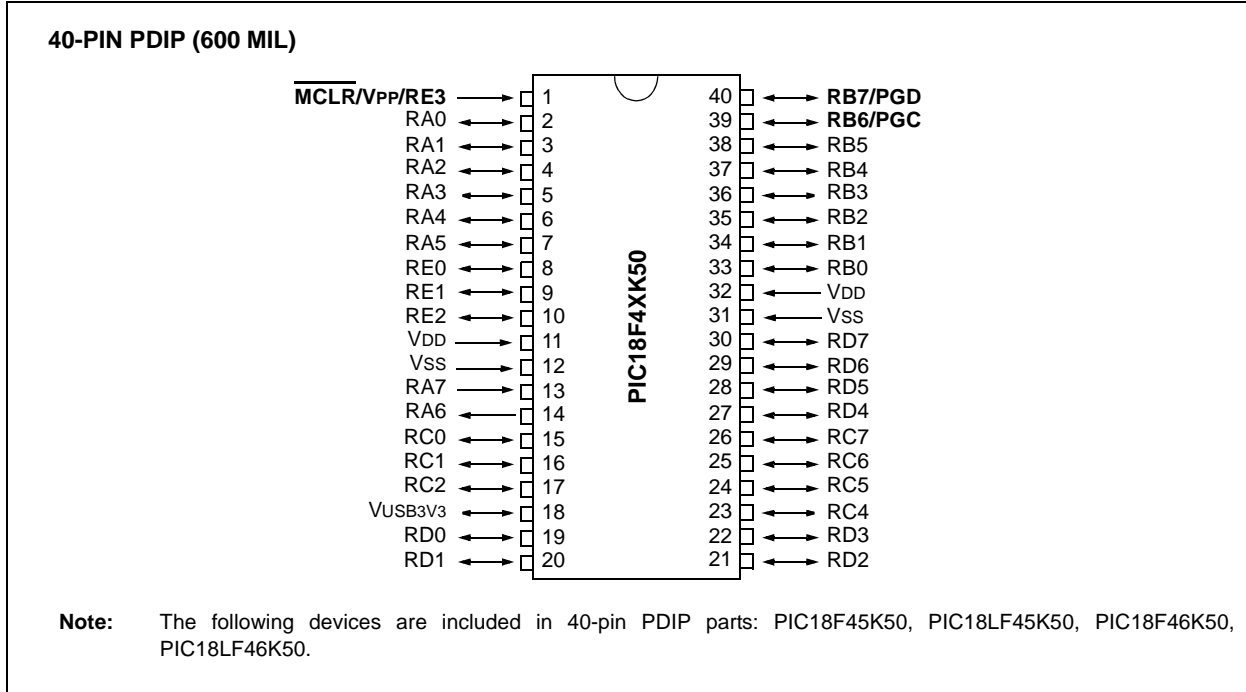


**FIGURE 2-2: 28-PIN QFN PIN DIAGRAMS**

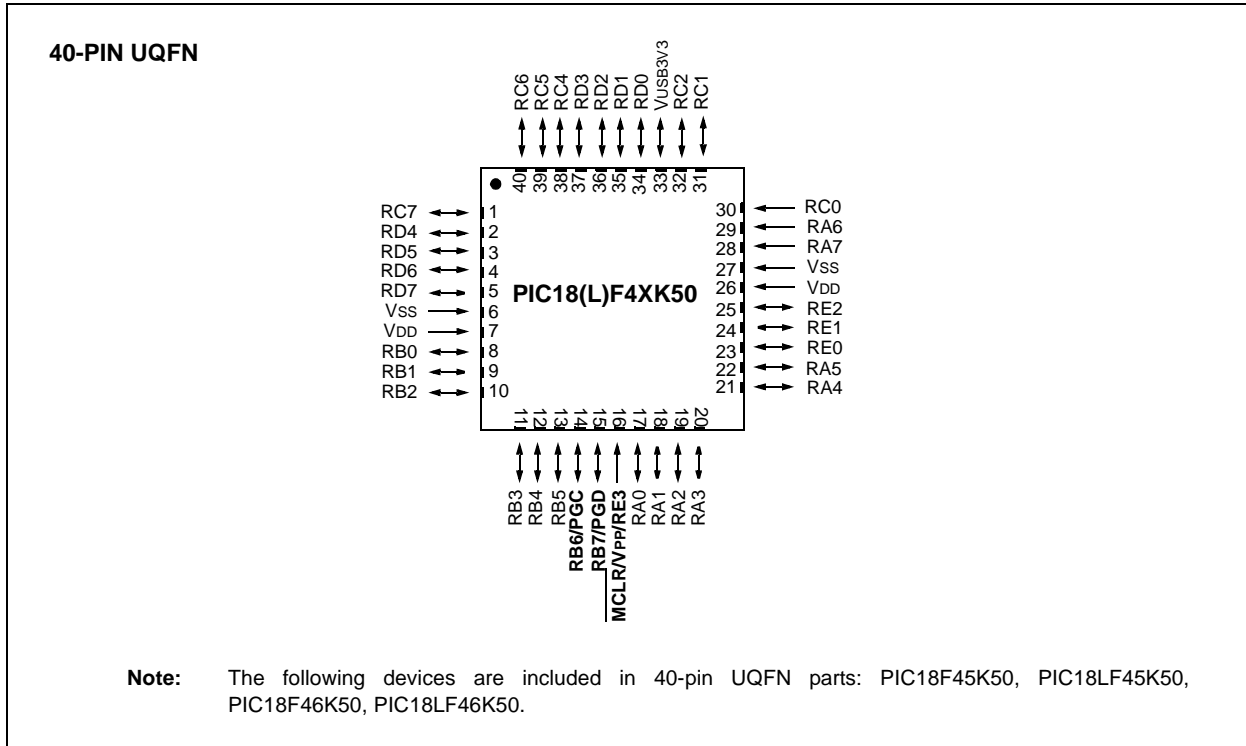


# PIC18(L)F2X/4XK50

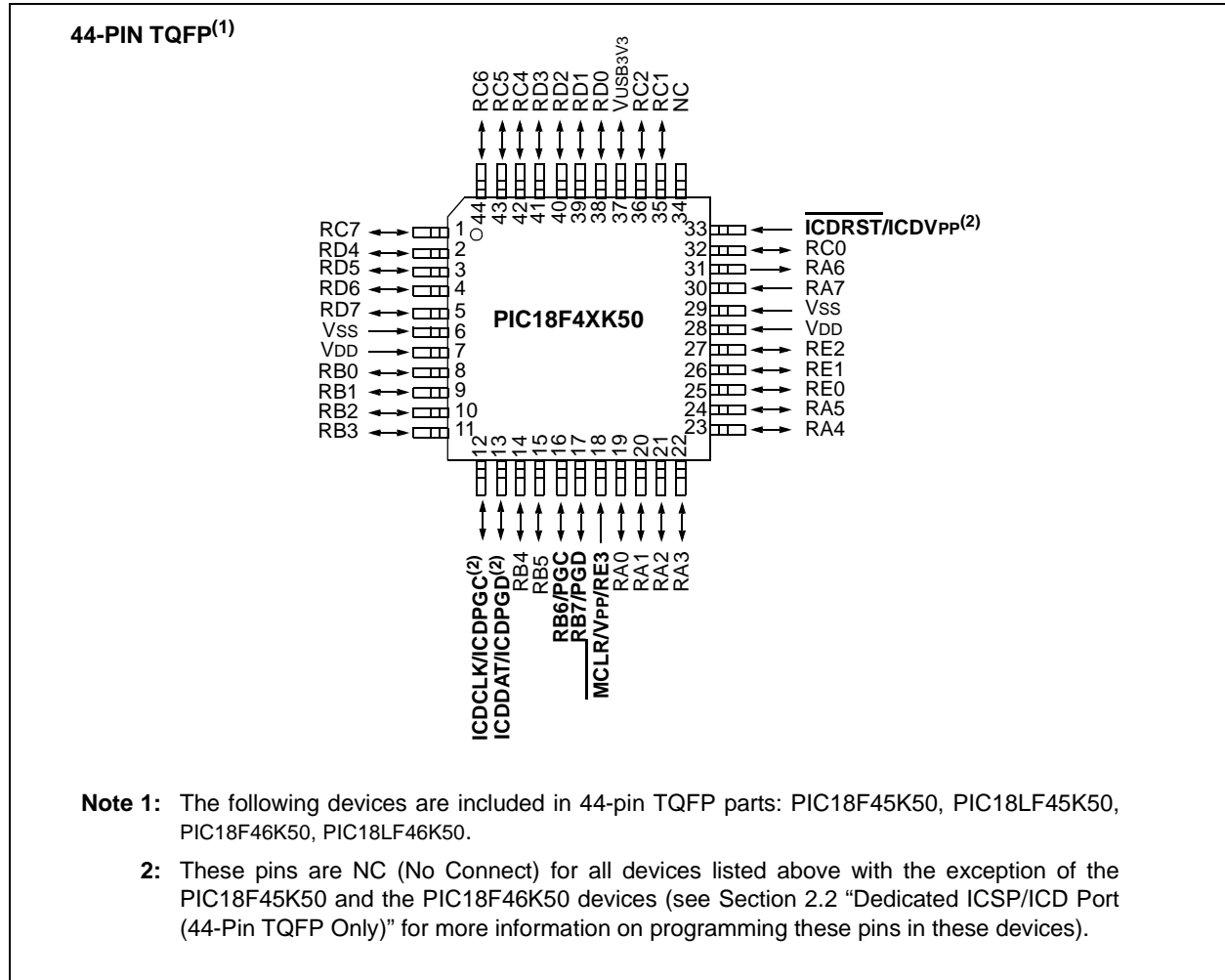
**FIGURE 2-3: 40-PIN PDIP PIN DIAGRAMS**



**FIGURE 2-4: 40-PIN UQFN PIN DIAGRAM**



**FIGURE 2-5: 44-PIN TQFP PIN DIAGRAM**



# PIC18(L)F2X/4XK50

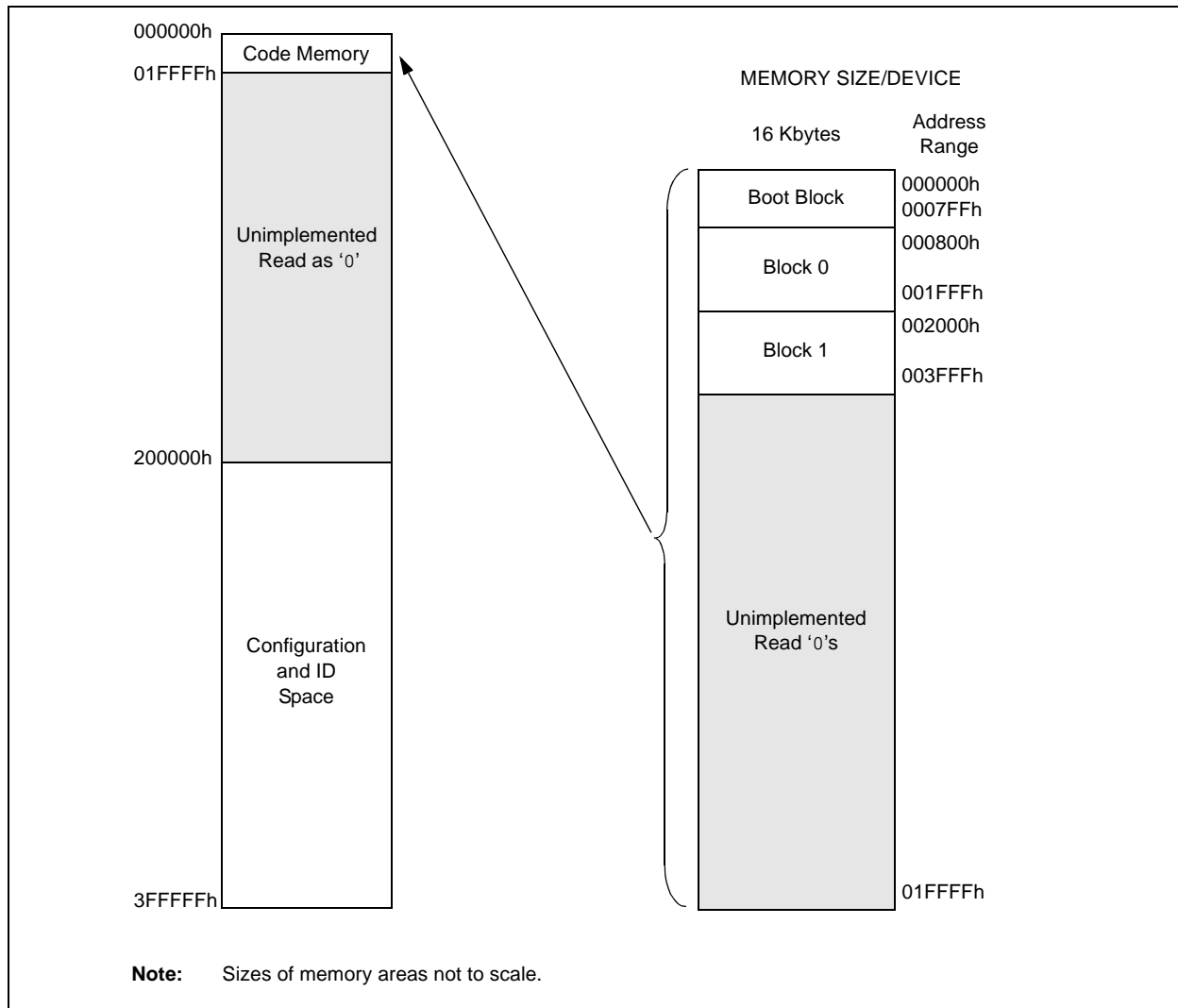
## 2.4 Memory Maps

For PIC18(L)F24K50 devices, the code memory space extends from 000000h to 003FFFh (16 Kbytes) in two 4-Kbyte blocks. Addresses 000000h through 0007FFh, however, define a “Boot Block” region that is treated separately from Block 0. All of these blocks define code protection boundaries within the code memory space.

**TABLE 2-2: IMPLEMENTATION OF CODE MEMORY**

Device	Code Memory Size (Bytes)
PIC18F24K50	000000h-003FFFh (16K)
PIC18LF24K50	

**FIGURE 2-6: MEMORY MAP AND THE CODE MEMORY SPACE FOR PIC18(L)F24K50 DEVICES**



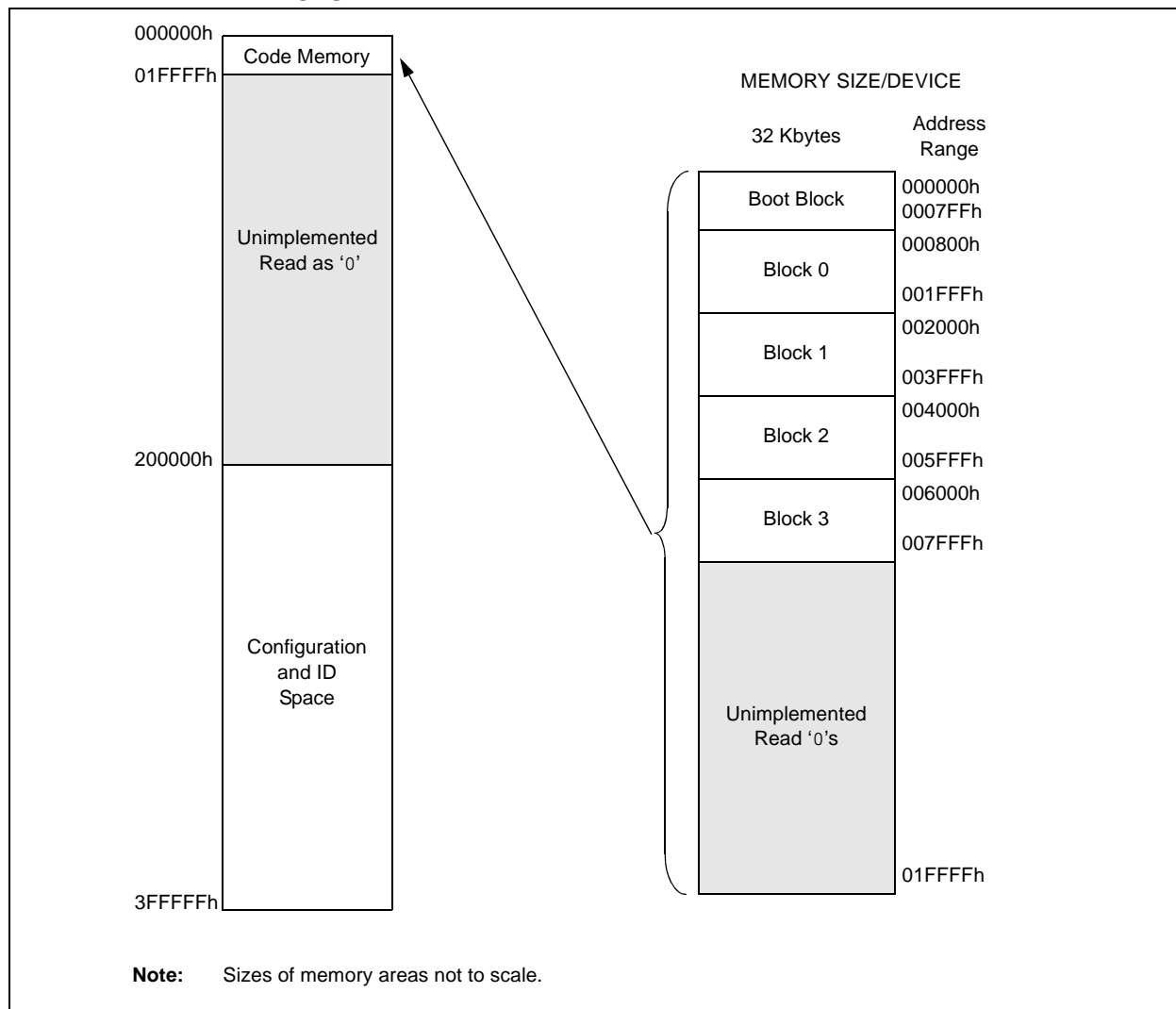
# PIC18(L)F2X/4XK50

For PIC18(L)FX5K50 devices, the code memory space extends from 000000h to 007FFFh (32 Kbytes) in four 8-Kbyte blocks. Addresses 000000h through 007FFFh, however, define a “Boot Block” region that is treated separately from Block 0. All of these blocks define code protection boundaries within the code memory space.

**TABLE 2-3: IMPLEMENTATION OF CODE MEMORY**

Device	Code Memory Size (Bytes)
PIC18F25K50	000000h-007FFFh (32K)
PIC18LF25K50	
PIC18F45K50	
PIC18LF45K50	

**FIGURE 2-7: MEMORY MAP AND THE CODE MEMORY SPACE FOR PIC18(L)FX5K50 DEVICES**



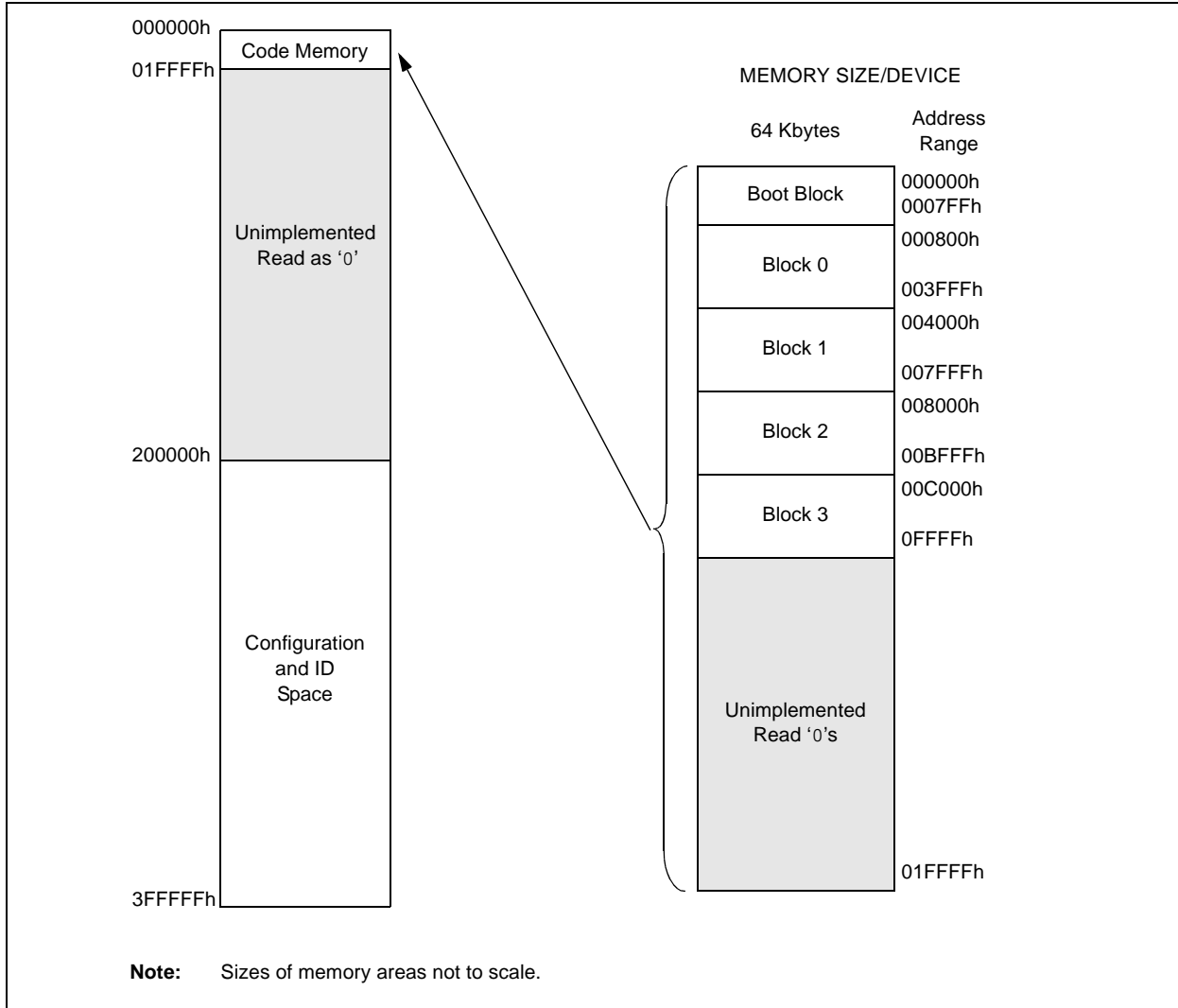
# PIC18(L)F2X/4XK50

For PIC18(L)FX6K50 devices, the code memory space extends from 000000h to 00FFFFh (64 Kbytes) in four 16-Kbyte blocks. Addresses 000000h through 0007FFh, however, define a “Boot Block” region that is treated separately from Block 0. All of these blocks define code protection boundaries within the code memory space.

**TABLE 2-4: IMPLEMENTATION OF CODE MEMORY**

Device	Code Memory Size (Bytes)
PIC18F26K50	000000h-00FFFFh (64K)
PIC18LF26K50	
PIC18F46K50	
PIC18LF46K50	

**FIGURE 2-8: MEMORY MAP AND THE CODE MEMORY SPACE FOR PIC18(L)FX6K50 DEVICES**





# PIC18(L)F2X/4XK50

In addition to the code memory space, there are three blocks in the configuration and ID space that are accessible to the user through table reads and table writes. Their locations in the memory map are shown in Figure 2-9.

Users may store identification information (ID) in eight ID registers. These ID registers are mapped in addresses 200000h through 200007h. The ID locations read out normally, even after code protection is applied.

Locations 300000h through 30000Dh are reserved for the Configuration bits. These bits select various device options and are described in Section 5.0 “Configuration Word”. These Configuration bits read out normally, even after code protection.

Locations 3FFFEh and 3FFFFh are reserved for the device ID bits. These bits may be used by the programmer to identify what device type is being programmed and are described in Section 5.0 “Configuration Word”. These device ID bits read out normally, even after code protection.

## 2.4.1 MEMORY ADDRESS POINTER

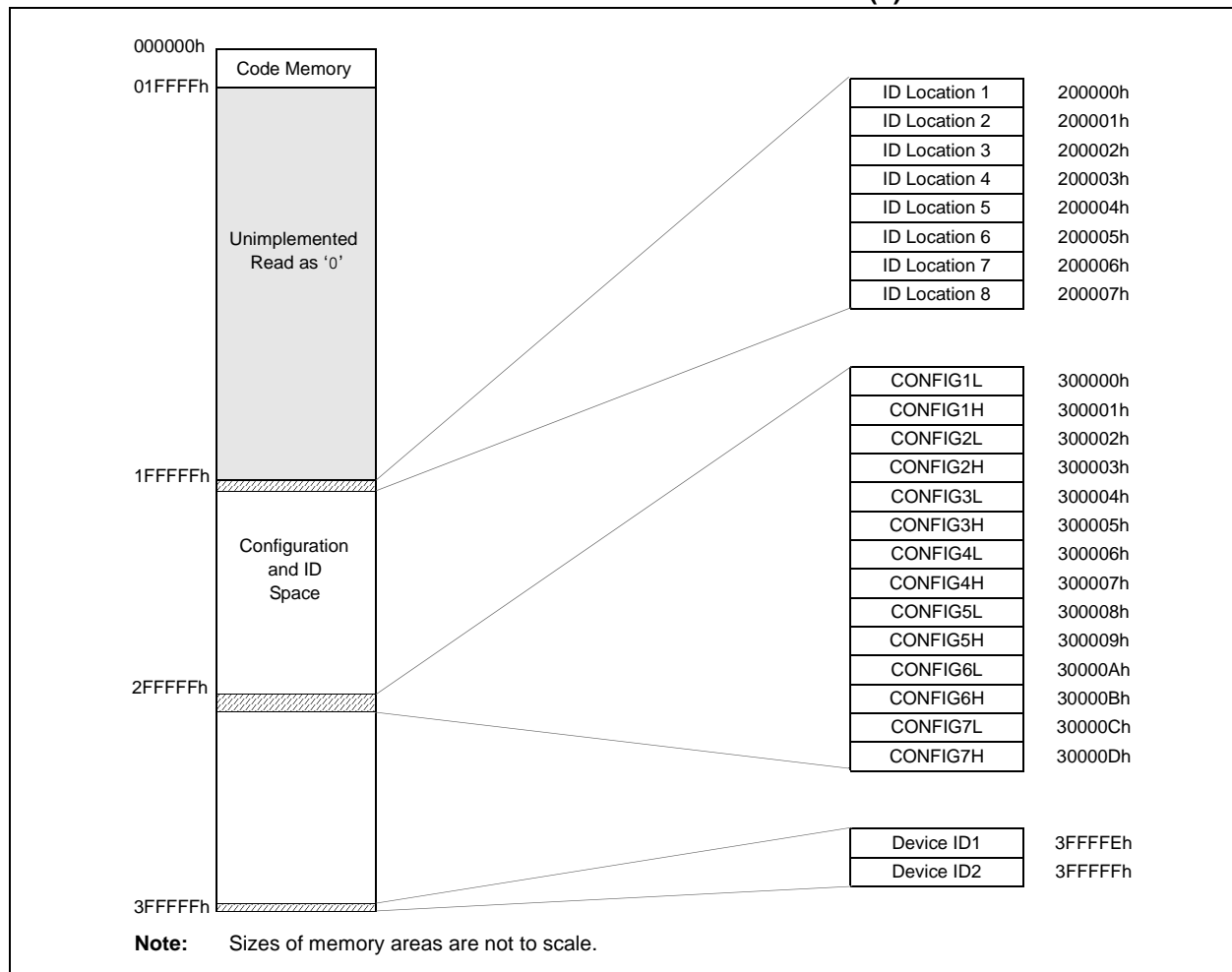
Memory in the address space, 0000000h to 3FFFFFFh, is addressed via the Table Pointer register, which is comprised of three Pointer registers:

- TBLPTRU, at RAM address 0FF8h
- TBLPTRH, at RAM address 0FF7h
- TBLPTRL, at RAM address 0FF6h

TBLPTRU	TBLPTRH	TBLPTRL
Addr[21:16]	Addr[15:8]	Addr[7:0]

The 4-bit command, '0000' (core instruction), is used to load the Table Pointer prior to using any read or write operations.

**FIGURE 2-9: CONFIGURATION AND ID LOCATIONS FOR PIC18(L)F2X/4XK50 DEVICES**

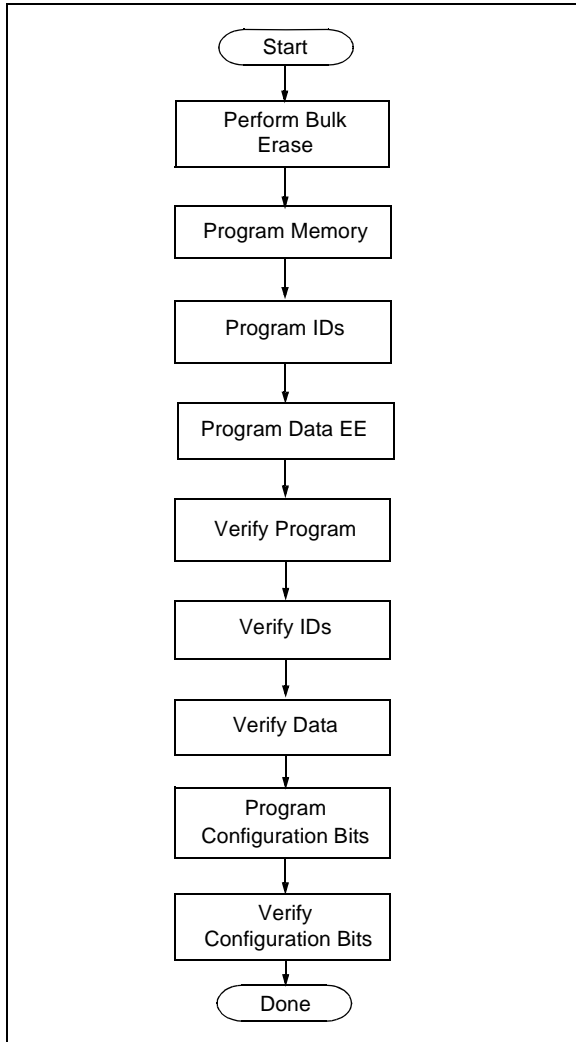


# PIC18(L)F2X/4XK50

## 2.5 High-Level Overview of the Programming Process

Figure 2-10 shows the high-level overview of the programming process. First, a Bulk Erase is performed. Next, the code memory, ID locations and data EEPROM are programmed. These memories are then verified to ensure that programming was successful. If no errors are detected, the Configuration bits are then programmed and verified.

**FIGURE 2-10: HIGH-LEVEL PROGRAMMING FLOW**

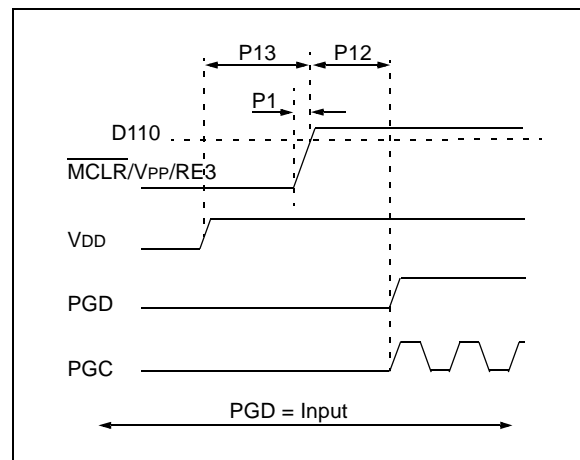


## 2.6 Entering and Exiting High-Voltage ICSP Program/Verify Mode

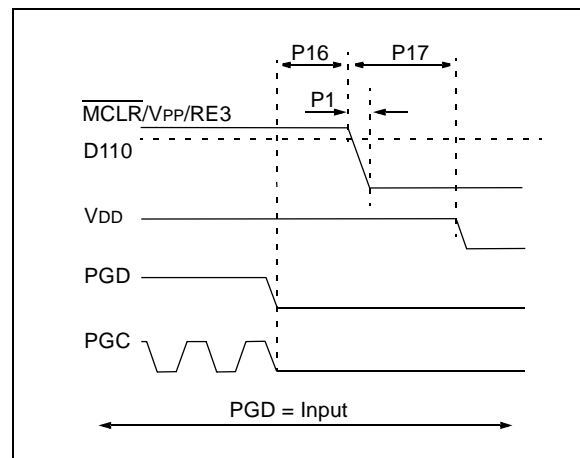
As shown in Figure 2-11, the High-Voltage ICSP Program/Verify mode is entered by holding PGC and PGD low and then raising  $\overline{\text{MCLR}}/\text{VPP}/\text{RE3}$  to  $V_{\text{IH}}\text{H}$  (high voltage). Once in this mode, the code memory, data EEPROM, ID locations and Configuration bits can be accessed and programmed in serial fashion. Figure 2-12 shows the exit sequence.

The sequence that enters the device into the Program/Verify mode places all unused I/Os in the high-impedance state.

**FIGURE 2-11: ENTERING HIGH-VOLTAGE PROGRAM/VERIFY MODE**



**FIGURE 2-12: EXITING HIGH-VOLTAGE PROGRAM/VERIFY MODE**



## 2.7 Entering and Exiting Low-Voltage ICSP Program/Verify Mode

As shown in Figure 2-13, entering ICSP Program/Verify mode requires three steps:

1. Voltage is briefly applied to the  $\overline{\text{MCLR}}$  pin.
2. A 32-bit key sequence is presented on PGD.
3. Voltage is reapplied to  $\overline{\text{MCLR}}$ .

The programming voltage applied to  $\overline{\text{MCLR}}$  is  $V_{IH}$ , or usually,  $V_{DD}$ . There is no minimum time requirement for holding at  $V_{IH}$ . After  $V_{IH}$  is removed, an interval of at least P18 must elapse before presenting the key sequence on PGD.

The key sequence is a specific 32-bit pattern, '0100 1101 0100 0011 0100 1000 0101 0000' (more easily remembered as 4D434850h in hexadecimal). The device will enter Program/Verify mode only if the sequence is valid. The Most Significant bit of the Most Significant nibble must be shifted in first.

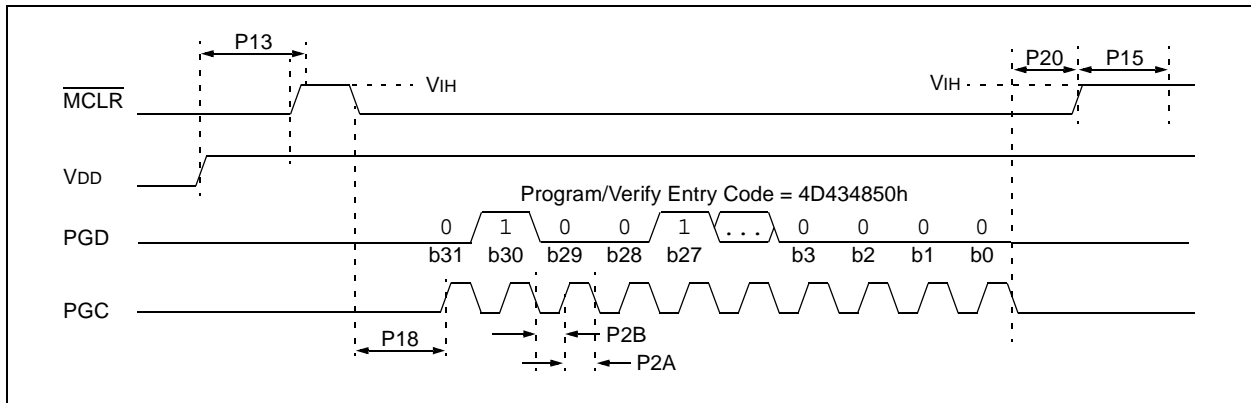
Once the key sequence is complete,  $V_{IH}$  must be applied to  $\overline{\text{MCLR}}$  and held at that level for as long as Program/Verify mode is to be maintained. An interval of at least time P20 and P15 must elapse before presenting data on PGD. Signals appearing on PGD before P15 has elapsed may not be interpreted as valid.

On successful entry, the program memory can be accessed and programmed in serial fashion. While in the Program/Verify mode, all unused I/Os are placed in the high-impedance state.

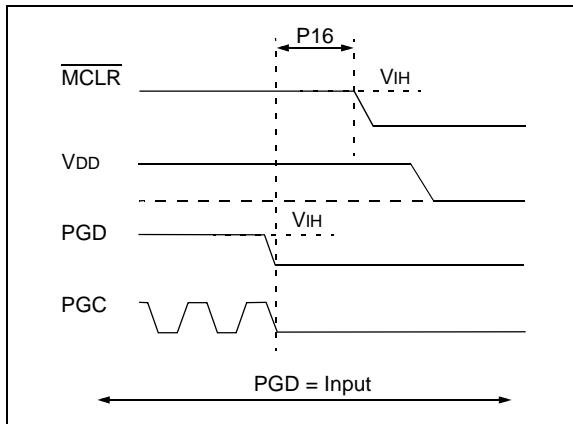
Exiting Program/Verify mode is done by removing  $V_{IH}$  from  $\overline{\text{MCLR}}$ , as shown in Figure 2-14. The only requirement for exit is that an interval, P16, should elapse between the last clock and the program signals on PGC and PGD before removing  $V_{IH}$ .

When  $V_{IH}$  is reapplied to  $\overline{\text{MCLR}}$ , the device will enter the ordinary operational mode and begin executing the application instructions.

**FIGURE 2-13: ENTERING LOW-VOLTAGE PROGRAM/VERIFY MODE**



**FIGURE 2-14: EXITING LOW-VOLTAGE PROGRAM/VERIFY MODE**



# PIC18(L)F2X/4XK50

## 2.8 Serial Program/Verify Operation

The PGC pin is used as a clock input pin and the PGD pin is used for entering command bits and data input/output during serial operation. Commands and data are transmitted on the rising edge of PGC, latched on the falling edge of PGC and are Least Significant bit (LSb) first.

### 2.8.1 4-BIT COMMANDS

All instructions are 20 bits, consisting of a leading 4-bit command followed by a 16-bit operand, which depends on the type of command being executed. To input a command, PGC is cycled four times. The commands needed for programming and verification are shown in Table 2-5.

Depending on the 4-bit command, the 16-bit operand represents 16 bits of input data or 8 bits of input data and 8 bits of output data.

Throughout this specification, commands and data are presented as illustrated in Table 2-6. The 4-bit command is shown Most Significant bit (MSb) first. The command operand, or "Data Payload", is shown <MSB><LSB>. Figure 2-15 demonstrates how to serially present a 20-bit command/operand to the device.

### 2.8.2 CORE INSTRUCTION

The core instruction passes a 16-bit instruction to the CPU core for execution. This is needed to set up registers as appropriate for use with other commands.

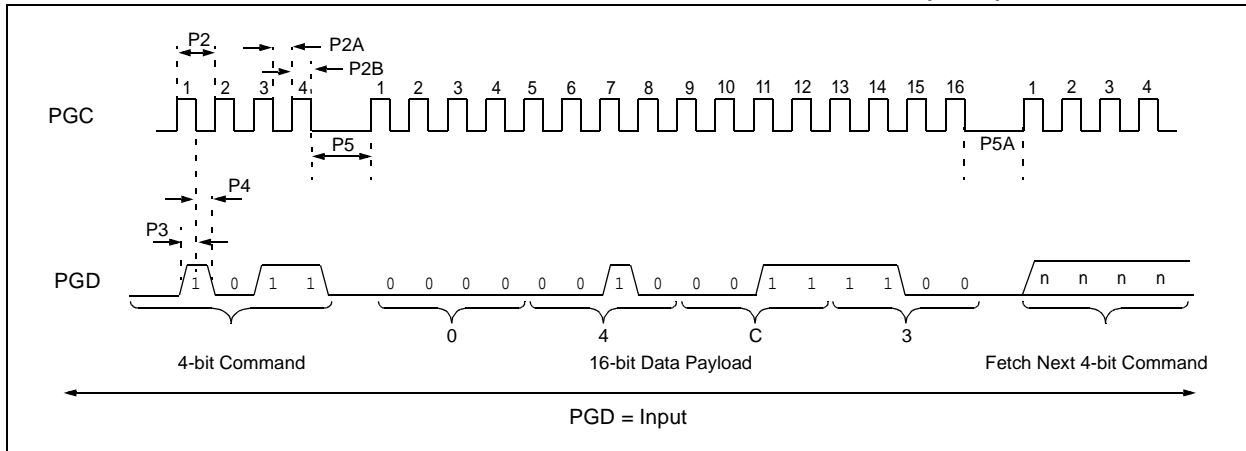
**TABLE 2-5: COMMANDS FOR PROGRAMMING**

Description	4-Bit Command
Core Instruction (Shift in 16-bit instruction)	0000
Shift out TABLAT register	0010
Table Read	1000
Table Read, post-increment	1001
Table Read, post-decrement	1010
Table Read, pre-increment	1011
Table Write	1100
Table Write, post-increment by 2	1101
Table Write, start programming, post-increment by 2	1110
Table Write, start programming	1111

**TABLE 2-6: SAMPLE COMMAND SEQUENCE**

4-Bit Command	Data Payload	Core Instruction
1101	3C 40	Table Write, post-increment by 2

**FIGURE 2-15: TABLE WRITE, POST-INCREMENT TIMING DIAGRAM (1101)**



## 3.0 DEVICE PROGRAMMING

Programming includes the ability to erase or write the various memory regions within the device.

In all cases, except high-voltage ICSP Bulk Erase, the EECON1 register must be configured in order to operate on a particular memory region.

When using the EECON1 register to act on code memory, the EEPGD bit must be set (EECON1<7> = 1) and the CFGS bit must be cleared (EECON1<6> = 0). The WREN bit must be set (EECON1<2> = 1) to enable writes of any sort (e.g., erases) and this must be done prior to initiating a write sequence. The FREE bit must be set (EECON1<4> = 1) in order to erase the program space being pointed to by the Table Pointer. The erase or write sequence is initiated by setting the WR bit (EECON1<1> = 1). It is strongly recommended that the WREN bit only be set immediately prior to a program or erase.

### 3.1 ICSP Erase

#### 3.1.1 HIGH-VOLTAGE ICSP BULK ERASE

Erasing code or data EEPROM is accomplished by configuring two Bulk Erase Control registers located at 3C0004h and 3C0005h. Code memory may be erased portions at a time, or the user may erase the entire device in one action. Bulk Erase operations will also clear any code-protect settings associated with the memory block erased. Erase options are detailed in Table 3-1. When any one or more blocks of code space are code protected, then all code blocks will be erased by default. If data EEPROM is code-protected (CPD = 0), the user must request an erase of data EEPROM (e.g., 0084h as shown in Table 3-1).

**TABLE 3-1: BULK ERASE OPTIONS**

Description	Data (3C0005h:3C0004h)
Chip Erase	0F8Fh
Erase User ID	0088h
Erase Data EEPROM	0084h
Erase Boot Block	0081h
Erase Config Bits	0082h
Erase Code EEPROM Block 0	0180h
Erase Code EEPROM Block 1	0280h
Erase Code EEPROM Block 2	0480h
Erase Code EEPROM Block 3	0880h

The actual Bulk Erase function is a self-timed operation. Once the erase has started (falling edge of the 4th PGC after the NOP command), serial execution will cease until the erase completes (parameter P11). During this time, PGC may continue to toggle but PGD must be held low.

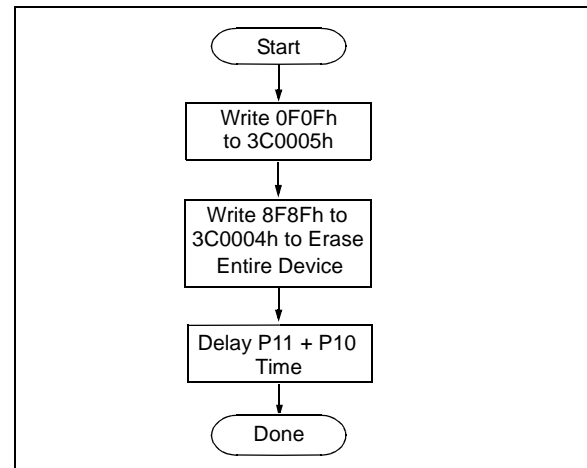
The code sequence to erase the entire device is shown in Table 3-2 and the flowchart is shown in Figure 3-1.

**Note:** A Bulk Erase is the only way to reprogram code-protect bits from an “on” state to an “off” state.

**TABLE 3-2: BULK ERASE COMMAND SEQUENCE**

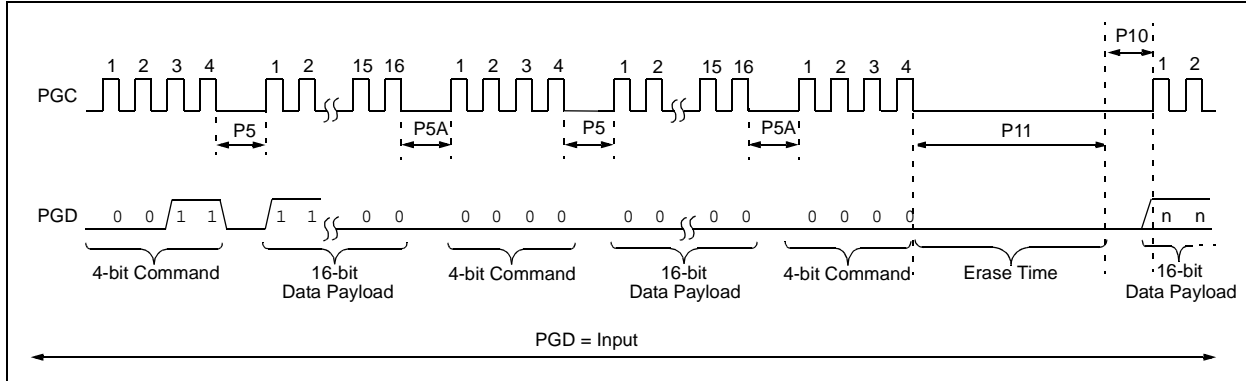
4-Bit Command	Data Payload	Core Instruction
0000	0E 3C	MOVLW 3Ch
0000	6E F8	MOVWF TBLPTRU
0000	0E 00	MOVLW 00h
0000	6E F7	MOVWF TBLPTRH
0000	0E 05	MOVLW 05h
0000	6E F6	MOVWF TBLPTRL
1100	0F 0F	Write 0Fh to 3C0005h
0000	0E 3C	MOVLW 3Ch
0000	6E F8	MOVWF TBLPTRU
0000	0E 00	MOVLW 00h
0000	6E F7	MOVWF TBLPTRH
0000	0E 04	MOVLW 04h
0000	6E F6	MOVWF TBLPTRL
1100	8F 8F	Write 8F8Fh TO 3C0004h to erase entire device.
0000	00 00	NOP
0000	00 00	Hold PGD low until erase completes.

**FIGURE 3-1: BULK ERASE FLOW**



# PIC18(L)F2X/4XK50

**FIGURE 3-2: BULK ERASE TIMING DIAGRAM**



### 3.1.2 LOW-VOLTAGE ICSP BULK ERASE

When using low-voltage ICSP, the part must be supplied by the voltage specified in parameter D111 if a Bulk Erase is to be executed. All other Bulk Erase details apply as described above.

If it is determined that a program memory erase must be performed at a supply voltage below the Bulk Erase limit, refer to the erase methodology described in [Section 3.1.3 “ICSP Row Erase”](#) and [Section 3.2.1 “Modifying Code Memory”](#).

If it is determined that a data EEPROM erase must be performed at a supply voltage below the Bulk Erase limit, follow the methodology described in [Section 3.3 “Data EEPROM Programming”](#) and write ‘1’s to the array.

### 3.1.3 ICSP ROW ERASE

Regardless of whether high or low-voltage ICSP is used, it is possible to erase one row (64 bytes of data), provided the block is not code or write-protected. Rows are located at static boundaries beginning at program memory address 000000h, extending to the internal program memory limit (see [Section 2.4 “Memory Maps”](#)).

The Row Erase duration is self-timed. After the WR bit in EECON1 is set, two NOPs are issued. Erase starts upon the 4th PGC of the second NOP. It ends when the WR bit is cleared by hardware.

The code sequence to Row Erase is shown in [Table 3-3](#). The flowchart shown in [Figure 3-3](#) depicts the logic necessary to completely erase the device. The timing diagram for Row Erase is identical to the data EEPROM write timing shown in [Figure 3-7](#).

**Note:** The TBLPTR register can point at any byte within the row intended for erase.

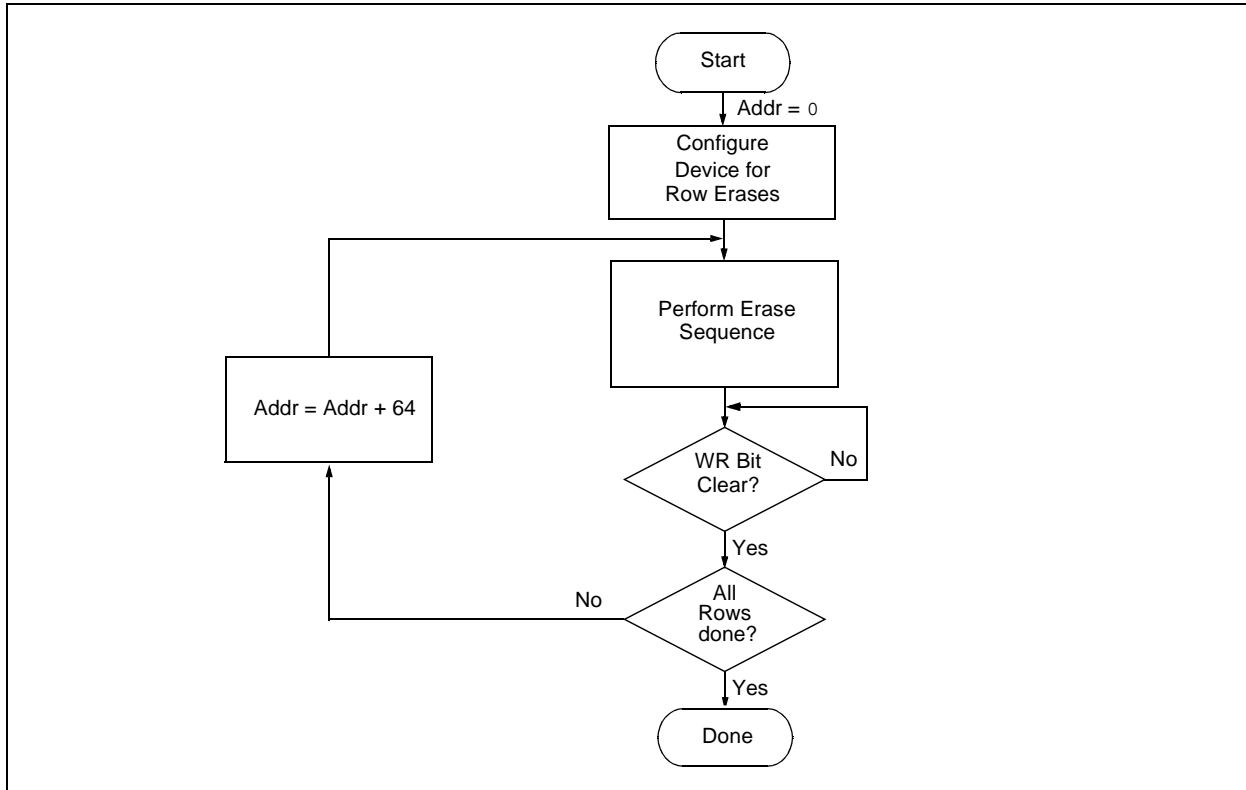
**TABLE 3-3: ERASE CODE MEMORY CODE SEQUENCE**

4-bit Command	Data Payload	Core Instruction
Step 1: Direct access to code memory and enable writes.		
0000	8E A6	BSF EECON1, EEPGD
0000	9C A6	BCF EECON1, CFGS
0000	84 A6	BSF EECON1, WREN
Step 2: Point to first row in code memory.		
0000	6A F8	CLRF TBLPTRU
0000	6A F7	CLRF TBLPTRH
0000	6A F6	CLRF TBLPTRL
Step 3: Enable erase and erase single row.		
0000	88 A6	BSF EECON1, FREE
0000	82 A6	BSF EECON1, WR
0000	00 00	NOP
0000	00 00	NOP Erase starts on the 4th clock of this instruction
Step 4: Poll WR bit. Repeat until bit is clear.		
0000	50 A6	MOVF EECON1, W, 0
0000	6E F5	MOVWF TABLAT
0000	00 00	NOP
0010	<MSB><LSB>	Shift out data <sup>(1)</sup>
Step 5: Hold PGC low for time P10.		
Step 6: Repeat Step 3 with Address Pointer incremented by 64 until all rows are erased.		
Step 7: Disable writes.		
0000	94 A6	BCF EECON1, WREN

**Note 1:** See [Figure 4-4](#) for details on shift out data timing.

# PIC18(L)F2X/4XK50

FIGURE 3-3: SINGLE ROW ERASE CODE MEMORY FLOW





## 3.2 Code Memory Programming

Programming code memory is accomplished by first loading data into the write buffer and then initiating a programming sequence. The write and erase buffer sizes shown in [Table 3-4](#) can be mapped to any location of the same size beginning at 000000h. The actual memory write sequence takes the contents of this buffer and programs the proper amount of code memory that contains the Table Pointer.

The programming duration is externally timed and is controlled by PGC. After a Start Programming command is issued (4-bit command, '1111'), a NOP is issued, where the 4th PGC is held high for the duration of the programming time, P9.

After PGC is brought low, the programming sequence is terminated. PGC must be held low for the time specified by parameter P10 to allow high-voltage discharge of the memory array.

The code sequence to program a device is shown in [Table 3-5](#). The flowchart shown in [Figure 3-4](#) depicts the logic necessary to completely write the device. The timing diagram that details the Start Programming command and parameters P9 and P10 is shown in [Figure 3-5](#).

**Note:** The TBLPTR register must point to the same region when initiating the programming sequence as it did when the write buffers were loaded.

**TABLE 3-4: WRITE AND ERASE BUFFER SIZES**

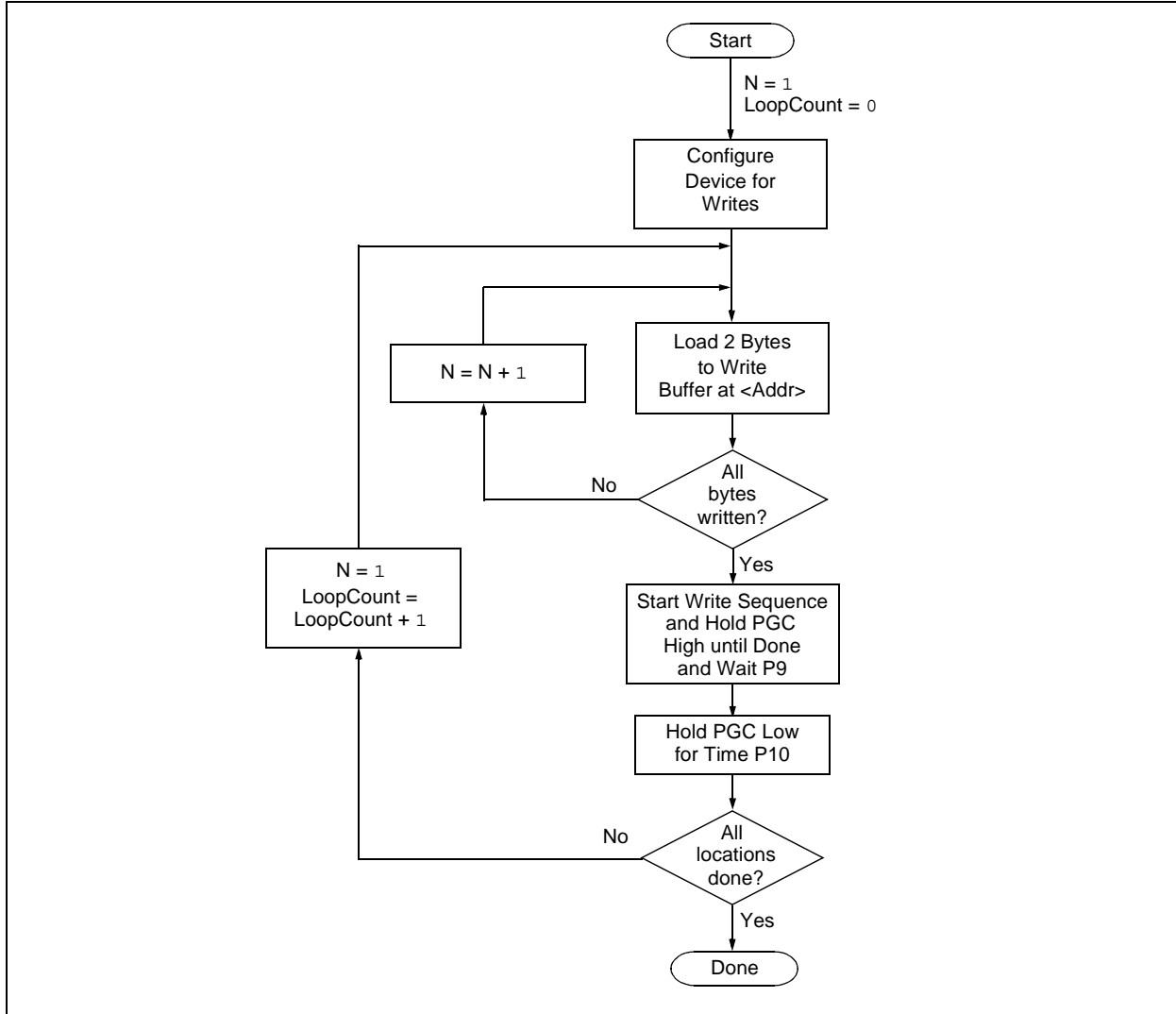
Devices				Write Buffer Size (bytes)	Erase Size (bytes)
PIC18F24K50	PIC18F45K50	PIC18LF24K50	PIC18LF45K50	64	64
PIC18F25K50	PIC18F46K50	PIC18LF25K50	PIC18LF46K50		
PIC18F26K50		PIC18LF26K50			

**TABLE 3-5: WRITE CODE MEMORY CODE SEQUENCE**

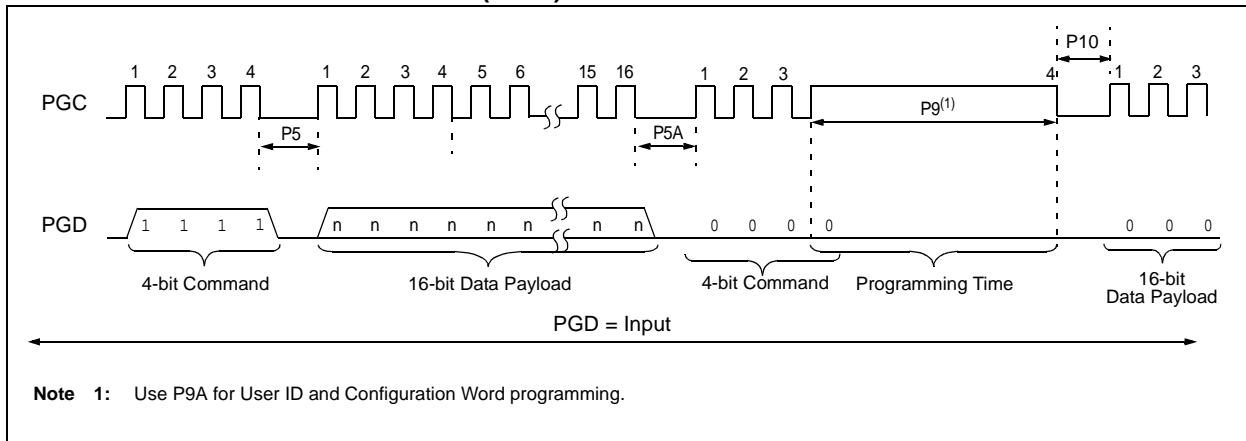
4-bit Command	Data Payload	Core Instruction
Step 1: Direct access to code memory.		
0000	8E A6	BSF EECON1, EEPGD
0000	9C A6	BCF EECON1, CFGS
0000	84 A6	BSF EECON1, WREN
Step 2: Point to row to write.		
0000	0E <Addr[21:16]>	MOVLW <Addr[21:16]>
0000	6E F8	MOVWF TBLPTRU
0000	0E <Addr[15:8]>	MOVLW <Addr[15:8]>
0000	6E F7	MOVWF TBLPTRH
0000	0E <Addr[7:0]>	MOVLW <Addr[7:0]>
0000	6E F6	MOVWF TBLPTRL
Step 3: Load write buffer. Repeat for all but the last two bytes.		
1101	<MSB><LSB>	Write 2 bytes and post-increment address by 2.
Step 4: Load write buffer for last two bytes and start programming.		
1111	<MSB><LSB>	Write 2 bytes and start programming.
0000	00 00	NOP - hold PGC high for time P9 and low for time P10.
To continue writing data, repeat Steps 2 through 4, where the Address Pointer is incremented by two at each iteration of the loop.		

# PIC18(L)F2X/4XK50

**FIGURE 3-4: PROGRAM CODE MEMORY FLOW**



**FIGURE 3-5: TABLE WRITE AND START PROGRAMMING INSTRUCTION TIMING DIAGRAM (1111)**



# PIC18(L)F2X/4XK50

## 3.2.1 MODIFYING CODE MEMORY

The previous programming example assumed that the device has been Bulk Erased prior to programming (see [Section 3.1.1 “High-Voltage ICSP Bulk Erase”](#)). It may be the case, however, that the user wishes to modify only a section of an already programmed device.

The appropriate number of bytes required for the erase buffer must be read out of code memory (as described in [Section 4.2 “Verify Code Memory and ID Locations”](#)) and buffered. Modifications can be made on this buffer. Then, the block of code memory that was read out must be erased and rewritten with the modified data.

The WREN bit must be set if the WR bit in EECON1 is used to initiate a write sequence.

**TABLE 3-6: MODIFYING CODE MEMORY**

4-bit Command	Data Payload	Core Instruction
Step 1: Direct access to code memory.		
0000	8E A6	BSF EECON1, EEPGD
0000	9C A6	BCF EECON1, CFGS
Step 2: Read code memory into buffer ( <a href="#">Section 4.1 “Read Code Memory, ID Locations and Configuration Bits”</a> ).		
Step 3: Set the Table Pointer for the block to be erased.		
0000	0E <Addr[21:16]>	MOVLW <Addr[21:16]>
0000	6E F8	MOVWF TBLPTRU
0000	0E <Addr[8:15]>	MOVLW <Addr[8:15]>
0000	6E F7	MOVWF TBLPTRH
0000	0E <Addr[7:0]>	MOVLW <Addr[7:0]>
0000	6E F6	MOVWF TBLPTRL
Step 4: Enable memory writes and setup an erase.		
0000	84 A6	BSF EECON1, WREN
0000	88 A6	BSF EECON1, FREE
Step 5: Initiate erase.		
0000	88 A6	BSF EECON1, FREE
0000	82 A6	BSF EECON1, WR
0000	00 00	NOP
0000	00 00	NOP Erase starts on the 4th clock of this instruction
Step 6: Poll WR bit. Repeat until bit is clear.		
0000	50 A6	MOVF EECON1, W, 0
0000	6E F5	MOVWF TABLAT
0000	00 00	NOP
0000	<MSB><LSB>	Shift out data <sup>(1)</sup>
Step 7: Load write buffer. The correct bytes will be selected based on the Table Pointer.		
0000	0E <Addr[21:16]>	MOVLW <Addr[21:16]>
0000	6E F8	MOVWF TBLPTRU
0000	0E <Addr[8:15]>	MOVLW <Addr[8:15]>
0000	6E F7	MOVWF TBLPTRH
0000	0E <Addr[7:0]>	MOVLW <Addr[7:0]>
0000	6E F6	MOVWF TBLPTRL
1101	<MSB><LSB>	Write 2 bytes and post-increment address by 2.
.	.	
.	.	Repeat as many times as necessary to fill the write buffer
.	.	Write 2 bytes and start programming.
1111	<MSB><LSB>	NOP - hold PGC high for time P9 and low for time P10.
0000	00 00	
To continue modifying data, repeat Steps 2 through 6, where the Address Pointer is incremented by the appropriate number of bytes (see <a href="#">Table 3-4</a> ) at each iteration of the loop. The write cycle must be repeated enough times to completely rewrite the contents of the erase buffer.		
Step 8: Disable writes.		
0000	94 A6	BCF EECON1, WREN

# PIC18(L)F2X/4XK50

## 3.3 Data EEPROM Programming

Data EEPROM is accessed one byte at a time via an Address Pointer (register pair EEADRH:EEADR) and a data latch (EEDATA). Data EEPROM is written by loading EEADRH:EEADR with the desired memory location, EEDATA, with the data to be written and initiating a memory write by appropriately configuring the EECON1 register. A byte write automatically erases the location and writes the new data (erase-before-write).

When using the EECON1 register to perform a data EEPROM write, both the EEPGD and CFGS bits must be cleared ( $EECON1\langle 7:6 \rangle = 00$ ). The WREN bit must be set ( $EECON1\langle 2 \rangle = 1$ ) to enable writes of any sort and this must be done prior to initiating a write sequence. The write sequence is initiated by setting the WR bit ( $EECON1\langle 1 \rangle = 1$ ).

The write begins on the falling edge of the 24th PGC after the WR bit is set. It ends when the WR bit is cleared by hardware.

After the programming sequence terminates, PGC must be held low for the time specified by parameter P10 to allow high-voltage discharge of the memory array.

FIGURE 3-6: PROGRAM DATA FLOW

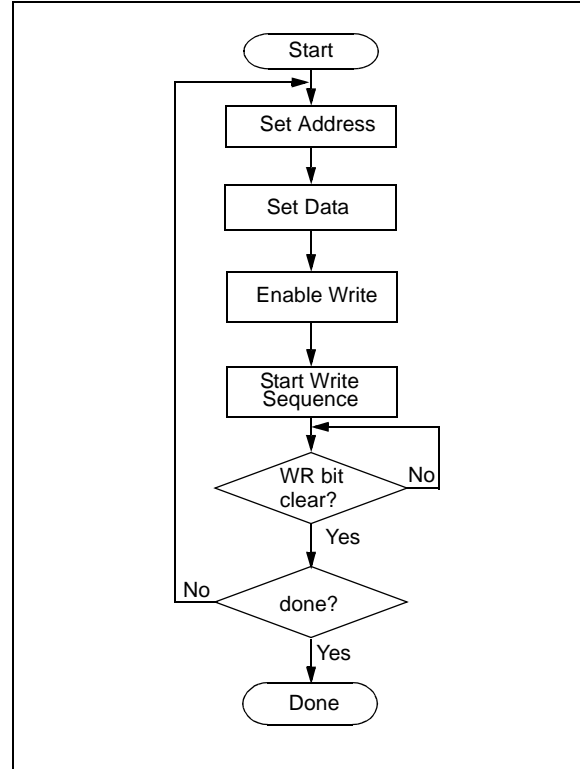
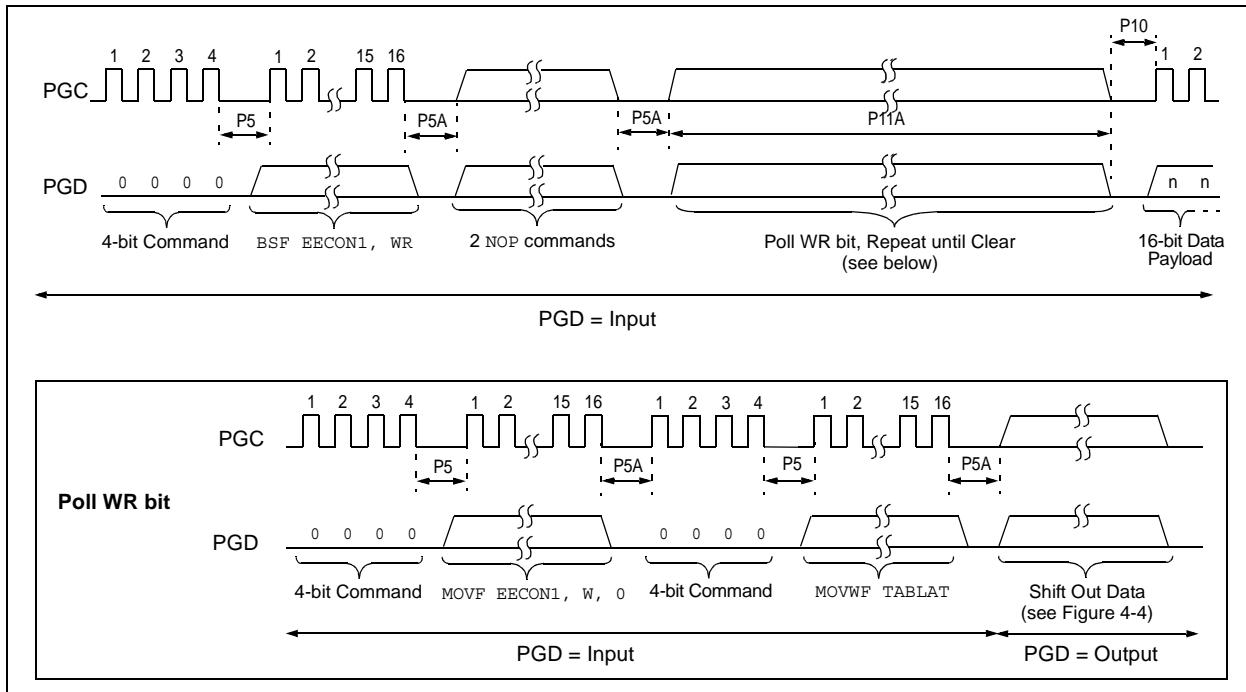


FIGURE 3-7: DATA EEPROM WRITE TIMING DIAGRAM



**TABLE 3-7: PROGRAMMING DATA MEMORY**

4-bit Command	Data Payload	Core Instruction
Step 1: Direct access to data EEPROM.		
0000	9E A6	BCF EECON1, EEPGD
0000	9C A6	BCF EECON1, CFGS
Step 2: Set the data EEPROM Address Pointer.		
0000	0E <Addr>	MOVLW <Addr>
0000	6E A9	MOVWF EEADR
0000	0E <AddrH>	MOVLW <AddrH>
0000	6E AA	MOVWF EEADRH
Step 3: Load the data to be written.		
0000	0E <Data>	MOVLW <Data>
0000	6E A8	MOVWF EEDATA
Step 4: Enable memory writes.		
0000	84 A6	BSF EECON1, WREN
Step 5: Initiate write.		
0000	82 A6	BSF EECON1, WR
0000	00 00	NOP
0000	00 00	NOP ;write starts on 4th clock of this instruction
Step 6: Poll WR bit, repeat until the bit is clear.		
0000	50 A6	MOVF EECON1, W, 0
0000	6E F5	MOVWF TABLAT
0000	00 00	NOP
0010	<MSB><LSB>	Shift out data <sup>(1)</sup>
Step 7: Hold PGC low for time P10.		
Step 8: Disable writes.		
0000	94 A6	BCF EECON1, WREN
Repeat steps 2 through 8 to write more data.		

**Note 1:** See [Figure 4-4](#) for details on shift out data timing.

# PIC18(L)F2X/4XK50

## 3.4 ID Location Programming

The ID locations are programmed much like the code memory. The ID registers are mapped in addresses 200000h through 200007h. These locations read out normally even after code protection.

**Note:** The user only needs to fill the first 8 bytes of the write buffer in order to write the ID locations.

In order to modify the ID locations, refer to the methodology described in [Section 3.2.1 “Modifying Code Memory”](#). As with code memory, the ID locations must be erased before being modified.

When VDD is below the minimum for Bulk Erase operation, ID locations can be cleared with the Row Erase method described in [Section 3.1.3 “ICSP Row Erase”](#).

[Table 3-8](#) demonstrates the code sequence required to write the ID locations.

**TABLE 3-8: WRITE ID SEQUENCE**

4-bit Command	Data Payload	Core Instruction
Step 1: Direct access to code memory.		
0000	8E A6	BSF EECON1, EEPGD
0000	9C A6	BCF EECON1, CFGS
0000	84 A6	BSF EECON1, WREN
Step 2: Set Table Pointer to ID. Load write buffer with 8 bytes and write.		
0000	0E 20	MOVLW 20h
0000	6E F8	MOVWF TBLPTRU
0000	0E 00	MOVLW 00h
0000	6E F7	MOVWF TBLPTRH
0000	0E 00	MOVLW 00h
0000	6E F6	MOVWF TBLPTRL
1101	<MSB><LSB>	Write 2 bytes and post-increment address by 2.
1101	<MSB><LSB>	Write 2 bytes and post-increment address by 2.
1101	<MSB><LSB>	Write 2 bytes and post-increment address by 2.
1111	<MSB><LSB>	Write 2 bytes and start programming.
0000	00 00	NOP - hold PGC high for time P9 and low for time P10.

## 3.5 Boot Block Programming

The code sequence detailed in [Table 3-5](#) should be used, except that the address used in “Step 2” will be in the range of 000000h to 0007FFh.

## 3.6 Configuration Bits Programming

Unlike code memory, the Configuration bits are programmed a byte at a time. The Table Write, Begin Programming 4-bit command ('1111') is used, but only 8 bits of the following 16-bit payload will be written. The LSB of the payload will be written to even addresses and the MSB will be written to odd addresses. The code sequence to program two consecutive configuration locations is shown in [Table 3-9](#). See [Figure 3-5](#) for the timing diagram.

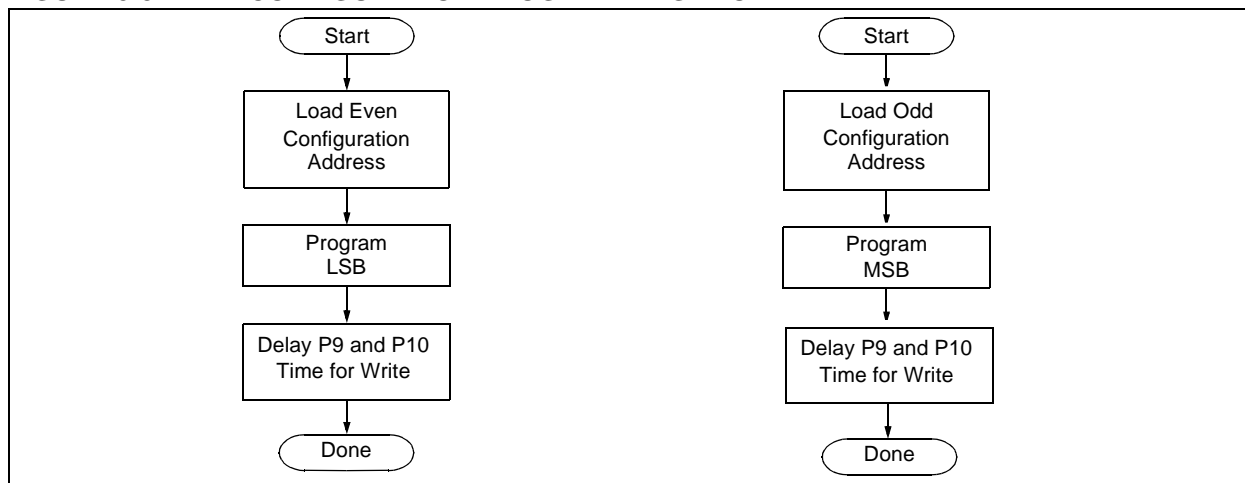
**Note:** The address must be explicitly written for each byte programmed. The addresses cannot be incremented in this mode.

**TABLE 3-9: SET ADDRESS POINTER TO CONFIGURATION LOCATION**

4-bit Command	Data Payload	Core Instruction
Step 1: Direct access to config memory.		
0000	8E A6	BSF EECON1, EEPGD
0000	8C A6	BSF EECON1, CFGS
0000	84 A6	BSF EECON1, WREN
Step 2 <sup>(1)</sup> : Set Table Pointer for config byte to be written. Write even/odd addresses.		
0000	0E 30	MOVLW 30h
0000	6E F8	MOVWF TBLPTRU
0000	0E 00	MOVLW 00h
0000	6E F7	MOVWF TBLPRTH
0000	0E 00	MOVLW 00h
0000	6E F6	MOVWF TBLPTRL
1111	<MSB ignored><LSB>	Load 2 bytes and start programming.
0000	00 00	NOP - hold PGC high for time P9 and low for time P10.
0000	0E 01	MOVLW 01h
0000	6E F6	MOVWF TBLPTRL
1111	<MSB><LSB ignored>	Load 2 bytes and start programming.
0000	00 00	NOP - hold PGC high for time P9A and low for time P10.

**Note 1:** Enabling the write protection of Configuration bits (WRTC = 0 in CONFIG6H) will prevent further writing of Configuration bits. Always write all the Configuration bits before enabling the write protection for Configuration bits.

**FIGURE 3-8: CONFIGURATION PROGRAMMING FLOW**



# PIC18(L)F2X/4XK50

## 4.0 READING THE DEVICE

### 4.1 Read Code Memory, ID Locations and Configuration Bits

Code memory is accessed one byte at a time via the 4-bit command, '1001' (table read, post-increment). The contents of memory pointed to by the Table Pointer (TBLPTRU:TBLPTRH:TBLPTRL) are serially output on PGD.

The 4-bit command is shifted in LSb first. The read is executed during the next 8 clocks, then shifted out on PGD during the last 8 clocks, LSb to MSb. A delay of P6 must be introduced after the falling edge of the 8th PGC of the operand to allow PGD to transition from an

input to an output. During this time, PGC must be held low (see Figure 4-1). This operation also increments the Table Pointer by one, pointing to the next byte in code memory for the next read.

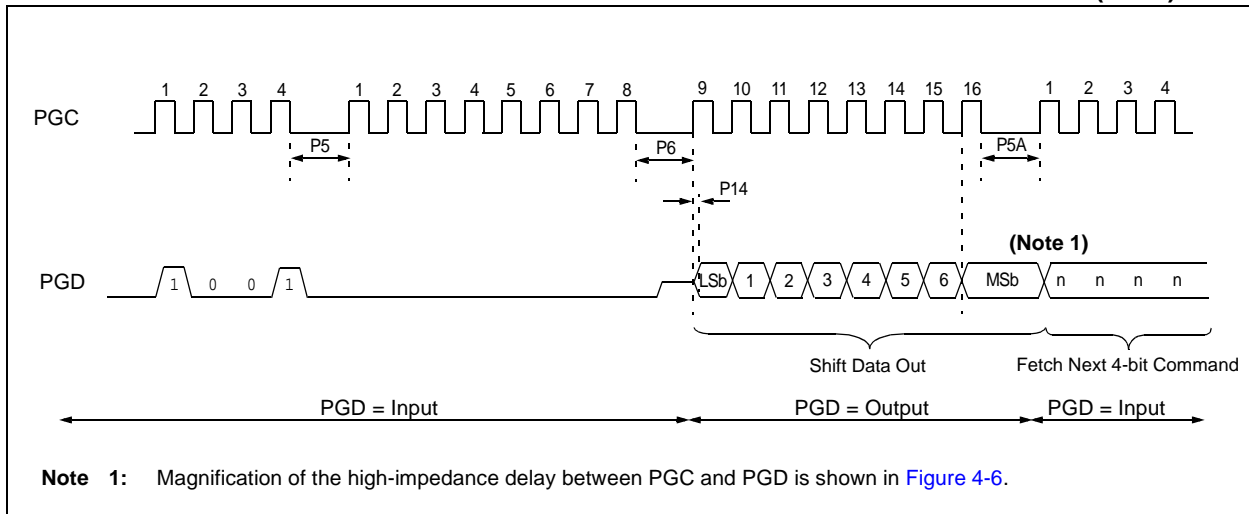
This technique will work to read any memory in the 000000h to 3FFFFFFh address space, so it also applies to the reading of the ID and Configuration registers.

**Note:** When table read protection is enabled, the first read access to a protected block should be discarded and the read repeated to retrieve valid data. Subsequent reads of the same block can be performed normally.

**TABLE 4-1: READ CODE MEMORY SEQUENCE**

4-bit Command	Data Payload	Core Instruction
Step 1: Set Table Pointer.		
0000	0E <Addr[21:16]>	MOVLW Addr[21:16]
0000	6E F8	MOVWF TBLPTRU
0000	0E <Addr[15:8]>	MOVLW <Addr[15:8]>
0000	6E F7	MOVWF TBLPTRH
0000	0E <Addr[7:0]>	MOVLW <Addr[7:0]>
0000	6E F6	MOVWF TBLPTRL
Step 2: Read memory and then shift out on PGD, LSb to MSb.		
1001	00 00	TBLRD *+

**FIGURE 4-1: TABLE READ POST-INCREMENT INSTRUCTION TIMING DIAGRAM (1001)**



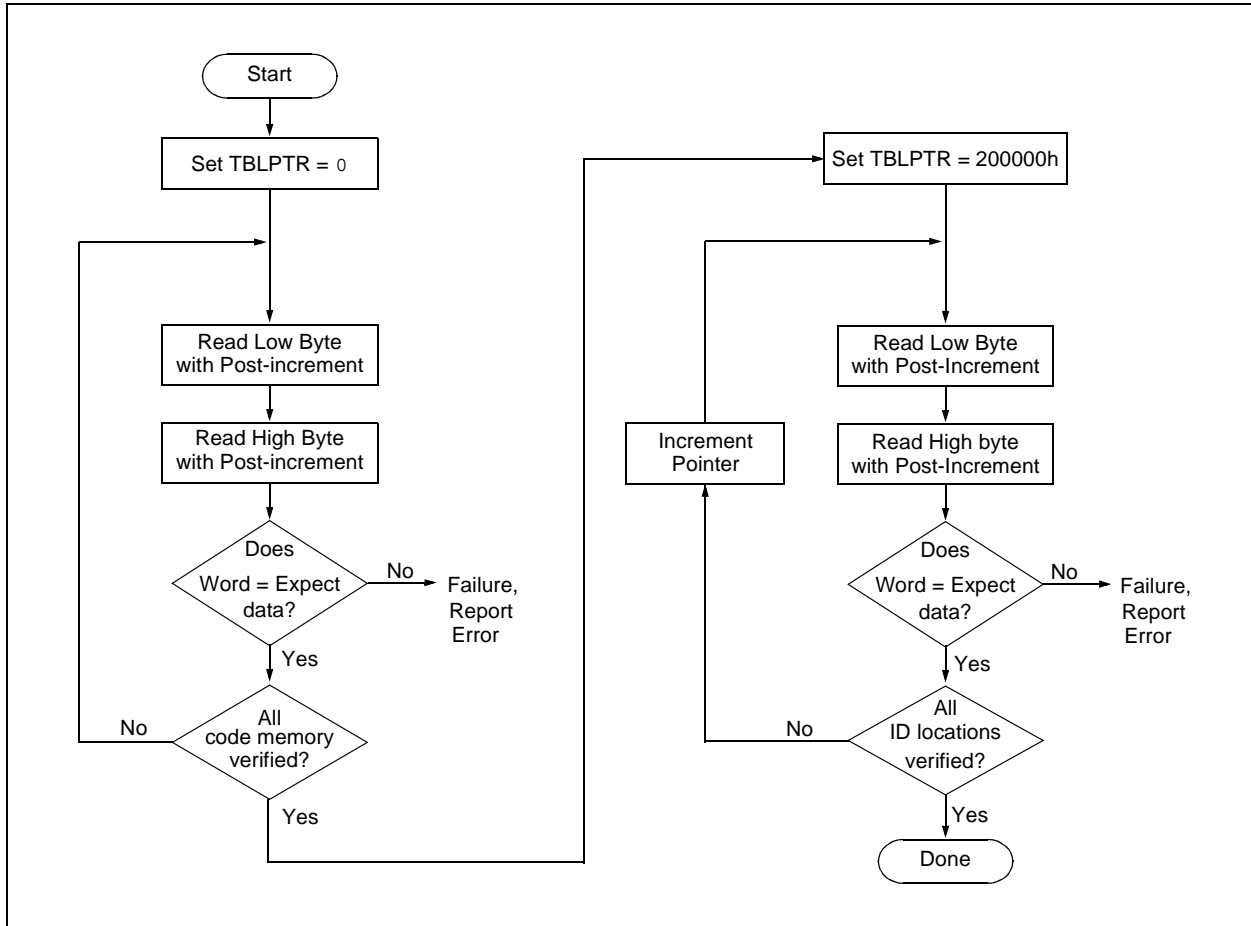


## 4.2 Verify Code Memory and ID Locations

The verify step involves reading back the code memory space and comparing it against the copy held in the programmer's buffer. Memory reads occur a single byte at a time, so two bytes must be read to compare against the word in the programmer's buffer. Refer to [Section 4.1 "Read Code Memory, ID Locations and Configuration Bits"](#) for implementation details of reading code memory.

The Table Pointer must be manually set to 200000h (base address of the ID locations) once the code memory has been verified. The post-increment feature of the table read 4-bit command cannot be used to increment the Table Pointer beyond the code memory space. In a 64-Kbyte device, for example, a post-increment read of address FFFFh will wrap the Table Pointer back to 000000h, rather than point to unimplemented address 010000h.

**FIGURE 4-2: VERIFY CODE MEMORY FLOW**



# PIC18(L)F2X/4XK50

## 4.3 Verify Configuration Bits

A configuration address may be read and output on PGD via the 4-bit command, '1001'. Configuration data is read and written in a byte-wise fashion, so it is not necessary to merge two bytes into a word prior to a compare. The result may then be immediately compared to the appropriate configuration data in the programmer's memory for verification. Refer to [Section 4.1 "Read Code Memory, ID Locations and Configuration Bits"](#) for implementation details of reading configuration data.

## 4.4 Read Data EEPROM Memory

Data EEPROM is accessed one byte at a time via an Address Pointer (register pair EEADRH:EEADR) and a data latch (EEDATA). Data EEPROM is read by loading EEADRH:EEADR with the desired memory location and initiating a memory read by appropriately configuring the EECON1 register. The data will be loaded into EEDATA, where it may be serially output on PGD via the 4-bit command, '0010' (Shift Out Data Holding register). A delay of P6 must be introduced after the falling edge of the 8th PGC of the operand to allow PGD to transition from an input to an output. During this time, PGC must be held low (see [Figure 4-4](#)).

The command sequence to read a single byte of data is shown in [Table 4-2](#).

FIGURE 4-3: READ DATA EEPROM FLOW

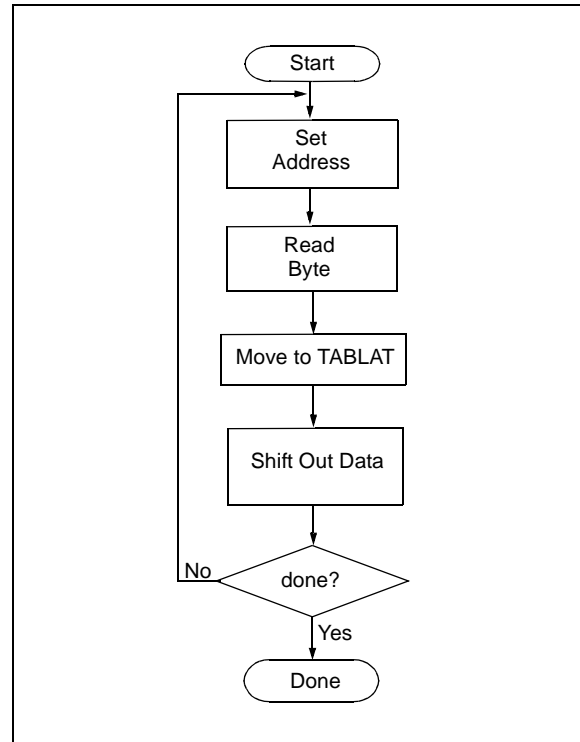
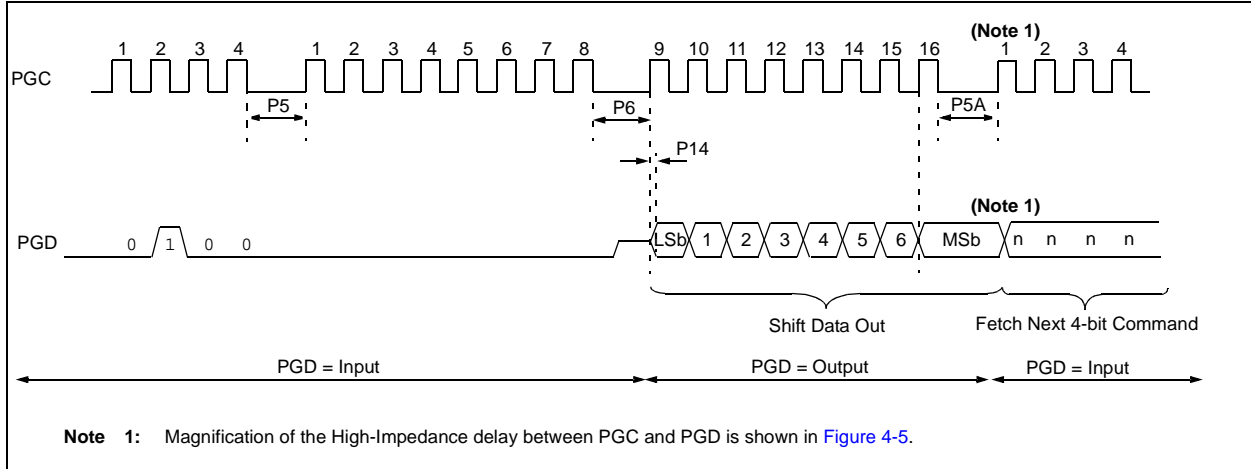


TABLE 4-2: READ DATA EEPROM MEMORY

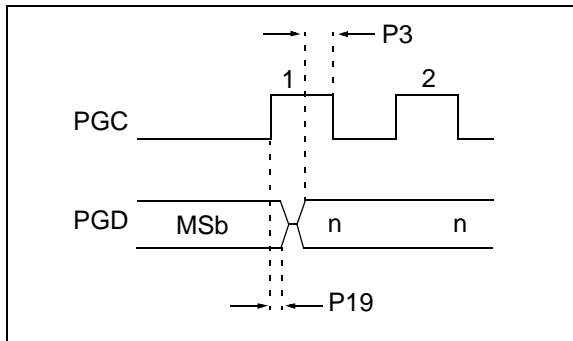
4-bit Command	Data Payload	Core Instruction
Step 1: Direct access to data EEPROM.		
0000	9E A6	BCF EECON1, EEPGD
0000	9C A6	BCF EECON1, CFGS
Step 2: Set the data EEPROM Address Pointer.		
0000	0E <Addr>	MOVLW <Addr>
0000	6E A9	MOVWF EEADR
0000	0E <AddrH>	MOVLW <AddrH>
0000	6E AA	MOVWF EEADRH
Step 3: Initiate a memory read.		
0000	80 A6	BSF EECON1, RD
Step 4: Load data into the Serial Data Holding register.		
0000	50 A8	MOVF EEDATA, W, 0
0000	6E F5	MOVWF TABLAT
0000	00 00	NOP
0010	<MSB><LSB>	Shift Out Data <sup>(1)</sup>

**Note 1:** The <LSB> is undefined. The <MSB> is the data.

**FIGURE 4-4: SHIFT OUT DATA HOLDING REGISTER TIMING DIAGRAM (0010)**



**FIGURE 4-5: HIGH-IMPEDANCE DELAY**



## 4.5 Verify Data EEPROM

A data EEPROM address may be read via a sequence of core instructions (4-bit command, '0000') and then output on PGD via the 4-bit command, '0010' (TABLAT register). The result may then be immediately compared to the appropriate data in the programmer's memory for verification. Refer to [Section 4.4 "Read Data EEPROM Memory"](#) for implementation details of reading data EEPROM.

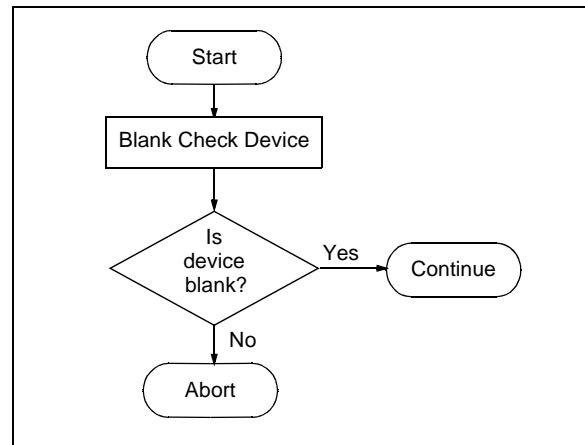
## 4.6 Blank Check

The term "Blank Check" means to verify that the device has no programmed memory cells. All memories must be verified: code memory, data EEPROM, ID locations and Configuration bits. The device ID registers (3FFFFEh:3FFFFFh) should be ignored.

A "blank" or "erased" memory cell will read as a '1'. Therefore, Blank Checking a device merely means to verify that all bytes read as FFh except the Configuration bits. Unused (reserved) Configuration bits will read '0' (programmed). Refer to [Table 5-1](#) for blank configuration expect data for the various PIC18(L)F2X/4XK50 devices.

Given that Blank Checking is merely code and data EEPROM verification with FFh expect data, refer to [Section 4.4 "Read Data EEPROM Memory"](#) and [Section 4.2 "Verify Code Memory and ID Locations"](#) for implementation details.

**FIGURE 4-6: BLANK CHECK FLOW**



# PIC18(L)F2X/4XK50

## 5.0 CONFIGURATION WORD

The PIC18(L)F2X/4XK50 devices have several Configuration Words. These bits can be set or cleared to select various device configurations. All other memory areas should be programmed and verified prior to setting Configuration Words. These bits may be read out normally, even after read or code protection. See [Table 5-1](#) for a list of Configuration bits and device IDs, and [Table 5-3](#) for the Configuration bit descriptions.

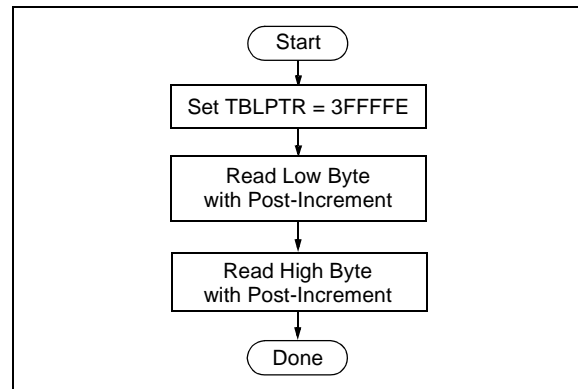
### 5.1 User ID Locations

A user may store identification information (ID) in eight ID locations mapped in 200000h:200007h. It is recommended that the Most Significant nibble of each ID be Fh. In doing so, if the user code inadvertently tries to execute from the ID space, the ID data will execute as a NOP.

## 5.2 Device ID Word

The device ID word for the PIC18(L)F2X/4XK50 devices is located at 3FFFEh:3FFFFh. These bits may be used by the programmer to identify what device type is being programmed and read out normally, even after code or read protection. See [Table 5-2](#) for a complete list of device ID values.

**FIGURE 5-1: READ DEVICE ID WORD FLOW**



**TABLE 5-1: CONFIGURATION BITS AND DEVICE IDs**

File Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Default/ Unprogrammed Value	
300000h	CONFIG1L	—	—	USBLSDIV	CPUDIV1	CPUDIV0	—	PLLEN <sup>(3)</sup>	PLLMULT <sup>(3)</sup>	--00 0-00
300001h	CONFIG1H	IESO	FCMEN	PCLKEN	—	FOSC3	FOSC2	FOSC1	FOSC0	001- 0101
300002h	CONFIG2L	—	LPBOR	—	BORV1	BORV0	BOREN1	BOREN0	PWRTEN	-1-1 1111
300003h	CONFIG2H	—	—	WDTPS3	WDTPS2	WDTPS1	WDTPS0	WDTEN1	WDTEN0	--11 1111
300005h	CONFIG3H	MCLRE	SDOMX	—	T3CMX	—	—	PBADEN	CCP2MX	11-1 --11
300006h	CONFIG4L	DEBUG	XINST	ICPRT	—	—	LVP	—	STVREN	101- -1-1
300008h	CONFIG5L	—	—	—	—	CP3 <sup>(1)</sup>	CP2 <sup>(1)</sup>	CP1	CP0	---- 1111
300009h	CONFIG5H	CPD	CPB	—	—	—	—	—	—	11-- ----
30000Ah	CONFIG6L	—	—	—	—	WRT3 <sup>(1)</sup>	WRT2 <sup>(1)</sup>	WRT1	WRT0	---- 1111
30000Bh	CONFIG6H	WRD	WRTB	WRTC	—	—	—	—	—	111- ----
30000Ch	CONFIG7L	—	—	—	—	EBTR3 <sup>(1)</sup>	EBTR2 <sup>(1)</sup>	EBTR1	EBTR0	---- 1111
30000Dh	CONFIG7H	—	EBTRB	—	—	—	—	—	—	-1-- ----
3FFFEh	DEVID1 <sup>(2)</sup>	DEV2	DEV1	DEV0	REV4	REV3	REV2	REV1	REV0	See <a href="#">Table 5-2</a>
3FFFFh	DEVID2 <sup>(2)</sup>	DEV10	DEV9	DEV8	DEV7	DEV6	DEV5	DEV4	DEV3	See <a href="#">Table 5-2</a>

**Legend:** x = unknown, u = unchanged, — = unimplemented. Shaded cells are unimplemented, read as '0'.

**Note 1:** These bits are only implemented on specific devices. Refer to [Section 2.4 "Memory Maps"](#) to determine which bits apply based on available memory.

**2:** DEVID registers are read-only and cannot be programmed by the user.

**3:** When the 3x Multiplier mode is selected, the input frequency has to be 16 MHz. When the 4x Multiplier mode is selected, the input frequency has to be between 8 MHz and 16 MHz.

# PIC18(L)F2X/4XK50

**TABLE 5-2: DEVICE ID VALUE**

Device	Device ID Value	
	DEVID2	DEVID1
PIC18F45K50	5Ch	000x xxxx
PIC18LF45K50	5Ch	100x xxxx
PIC18F25K50	5Ch	001x xxxx
PIC18LF25K50	5Ch	101x xxxx
PIC18F24K50	5Ch	011x xxxx
PIC18LF24K50	5Ch	111x xxxx
PIC18F26K50	5Dh	001x xxxx
PIC18LF26K50	5Dh	011x xxxx
PIC18F46K50	5Dh	000x xxxx
PIC18LF46K50	5Dh	010x xxxx

**Note:** The 'x's in DEVID1 contain the device revision code.

# PIC18(L)F2X/4XK50

**TABLE 5-3: PIC18(L)F2X/4XK50 BIT DESCRIPTIONS**

Bit Name	Configuration Words	Description
USBLSDIV	CONFIG1L	USB Low-Speed Clock Selection bit Selects the clock source for Low-speed USB operation 1 = USB clock source comes from the 48 MHz system clock divided by 8 0 = USB clock source comes from the 24 MHz system clock divided by 4
CPUDIV<1:0>	CONFIG1L	CPU System Clock Selection bits 11 = CPU system clock divided by 6 10 = CPU system clock divided by 3 01 = CPU system clock divided by 2 00 = No CPU system clock divide
PLLEN	CONFIG1L	PLL Enable bit <sup>(2)</sup> 1 = Oscillator multiplied by 3 or 4, depending on the PLLMULT bit 0 = Oscillator used directly
PLLMULT	CONFIG1L	PLL Multiplier Selection bit <sup>(2)</sup> 1 = Output frequency is 3x the input frequency 0 = Output frequency is 4x the input frequency
IESO	CONFIG1H	Internal External Switchover bit 1 = Internal External Switchover mode enabled 0 = Internal External Switchover mode disabled
FCMEN	CONFIG1H	Fail-Safe Clock Monitor Enable bit 1 = Fail-Safe Clock Monitor enabled 0 = Fail-Safe Clock Monitor disabled
PCLKEN	CONFIG1H	Primary Clock Enable bit 1 = Primary clock enabled 0 = Primary clock disabled
FOSC<3:0>	CONFIG1H	Oscillator Selection bits 1111 = External RC oscillator, CLKOUT function on OSC2 1110 = External RC oscillator, CLKOUT function on OSC2 1101 = EC oscillator (low power) 1100 = EC oscillator, CLKOUT function on OSC2 (low power) 1011 = EC oscillator (medium power, 4 MHz-16 MHz) 1010 = EC oscillator, CLKOUT function on OSC2 (medium power, 4 MHz-16 MHz) 1001 = Internal RC oscillator, CLKOUT function on OSC2 1000 = Internal RC oscillator 0111 = External RC oscillator 0110 = External RC oscillator, CLKOUT function on OSC2 0101 = EC oscillator (high power, >16 MHz) 0100 = EC oscillator, CLKOUT function on OSC2 (high power, >16 MHz) 0011 = HS oscillator (medium power, 4 MHz-16 MHz) 0010 = HS oscillator (high power, >16 MHz) 0001 = XT oscillator 0000 = LP oscillator
LPBOR	CONFIG2L	Low-Power Brown-out Reset Enable bits 1 = Low-Power Brown-out Reset disabled 0 = Low-Power Brown-out Reset enabled

**Note 1:** Minimum VDD for F devices is 2.3V.

**2:** When the 3x Multiplier mode is selected, the input frequency has to be 16 MHz. When the 4x Multiplier mode is selected, the input frequency has to be between 8 MHz and 16 MHz.

**3:** The dedicated In-Circuit Port is available only on the 44-pin TQFP packaged devices. This bit should be programmed to a '0' in all other devices. See [Section 2.2 "Dedicated ICSP/ICD Port \(44-Pin TQFP Only\)"](#) for more information.

# PIC18(L)F2X/4XK50

**TABLE 5-3: PIC18(L)F2X/4XK50 BIT DESCRIPTIONS (CONTINUED)**

Bit Name	Configuration Words	Description
BORV<1:0>	CONFIG2L	Brown-out Reset Voltage bits 11 = VBOR set to 1.9V <sup>(1)</sup> 10 = VBOR set to 2.2V <sup>(1)</sup> 01 = VBOR set to 2.5V 00 = VBOR set to 2.85V
BOREN<1:0>	CONFIG2L	Brown-out Reset Enable bits 11 = Brown-out Reset enabled in hardware only (SBOREN is disabled) 10 = Brown-out Reset enabled in hardware only and disabled in Sleep mode (SBOREN is disabled) 01 = Brown-out Reset enabled and controlled by software (SBOREN is enabled) 00 = Brown-out Reset disabled in hardware and software
PWRTEN	CONFIG2L	Power-up Timer Enable bit 1 = PWRT disabled 0 = PWRT enabled
WDTPS<3:0>	CONFIG2H	Watchdog Timer Postscaler Select bits 1111 = 1:32,768 1110 = 1:16,384 1101 = 1:8,192 1100 = 1:4,096 1011 = 1:2,048 1010 = 1:1,024 1001 = 1:512 1000 = 1:256 0111 = 1:128 0110 = 1:64 0101 = 1:32 0100 = 1:16 0011 = 1:8 0010 = 1:4 0001 = 1:2 0000 = 1:1
WDTEN<1:0>	CONFIG2H	Watchdog Timer Enable bits 11 = WDT enabled in hardware; SWDTEN bit is disabled 10 = WDT controlled by the SWDTEN bit 01 = WDT enabled when device is active, disabled when device is in Sleep; SWDTEN bit is disabled 00 = WDT disabled in hardware; SWDTEN bit is disabled
MCLR	CONFIG3H	MCLR Pin Enable bit 1 = MCLR pin enabled, RE3 input pin disabled 0 = RE3 input pin enabled, MCLR pin disabled
SDOMX	CONFIG3H	SDO Output MUX bit 1 = SDO is on RB3 0 = SDO is on RC7
T3CMX	CONFIG3H	Timer3 Clock Input MUX bit 1 = T3CKI is on RC0 0 = T3CKI is on RB5

**Note 1:** Minimum VDD for F devices is 2.3V.

- 2:** When the 3x Multiplier mode is selected, the input frequency has to be 16 MHz. When the 4x Multiplier mode is selected, the input frequency has to be between 8 MHz and 16 MHz.
- 3:** The dedicated In-Circuit Port is available only on the 44-pin TQFP packaged devices. This bit should be programmed to a '0' in all other devices. See [Section 2.2 "Dedicated ICSP/ICD Port \(44-Pin TQFP Only\)"](#) for more information.

# PIC18(L)F2X/4XK50

TABLE 5-3: PIC18(L)F2X/4XK50 BIT DESCRIPTIONS (CONTINUED)

Bit Name	Configuration Words	Description
PBADEN	CONFIG3H	PORTB A/D Enable bit 1 = PORTB A/D<5:0> pins are configured as analog input channels on Reset 0 = PORTB A/D<5:0> pins are configured as digital I/O on Reset
CCP2MX	CONFIG3H	CCP2 MUX bit 1 = CCP2 input/output is multiplexed with RC1 0 = CCP2 input/output is multiplexed with RB3
DEBUG	CONFIG4L	Background Debugger Enable bit 1 = Background debugger disabled, RB6 and RB7 configured as general purpose I/O pins 0 = Background debugger enabled, RB6 and RB7 are dedicated to In-Circuit Debug
XINST	CONFIG4L	Extended Instruction Set Enable bit 1 = Instruction set extension and Indexed Addressing mode enabled 0 = Instruction set extension and Indexed Addressing mode disabled (Legacy mode)
ICPRT	CONFIG4L	Dedicated In-Circuit (ICD/ICSP) Port Enable bit <sup>(3)</sup> 1 = ICPRT enabled 0 = ICPRT disabled
LVP	CONFIG4L	Low-Voltage Programming Enable bit If MCLRE = 1, then: 1 = Low-voltage programming enabled 0 = Low-voltage programming disabled If MCLRE = 0, then: LVP is disabled
STVREN	CONFIG4L	Stack Overflow/Underflow Reset Enable bit 1 = Reset on Stack Overflow/Underflow enabled 0 = Reset on Stack Overflow/Underflow disabled

**Note 1:** Minimum V<sub>DD</sub> for F devices is 2.3V.

**2:** When the 3x Multiplier mode is selected, the input frequency has to be 16 MHz. When the 4x Multiplier mode is selected, the input frequency has to be between 8 MHz and 16 MHz.

**3:** The dedicated In-Circuit Port is available only on the 44-pin TQFP packaged devices. This bit should be programmed to a '0' in all other devices. See [Section 2.2 “Dedicated ICSP/ICD Port \(44-Pin TQFP Only\)”](#) for more information.



# PIC18(L)F2X/4XK50

**TABLE 5-3: PIC18(L)F2X/4XK50 BIT DESCRIPTIONS (CONTINUED)**

Bit Name	Configuration Words	Description
CP3	CONFIG5L	Code Protection bits (Block 3 code memory area) 1 = Block 3 is not code-protected 0 = Block 3 is code-protected
CP2	CONFIG5L	Code Protection bits (Block 2 code memory area) 1 = Block 2 is not code-protected 0 = Block 2 is code-protected
CP1	CONFIG5L	Code Protection bits (Block 1 code memory area) 1 = Block 1 is not code-protected 0 = Block 1 is code-protected
CP0	CONFIG5L	Code Protection bits (Block 0 code memory area) 1 = Block 0 is not code-protected 0 = Block 0 is code-protected
CPD	CONFIG5H	Code Protection bits (Data EEPROM) 1 = Data EEPROM is not code-protected 0 = Data EEPROM is code-protected
CPB	CONFIG5H	Code Protection bits (Boot Block memory area) 1 = Boot Block is not code-protected 0 = Boot Block is code-protected
WRT3	CONFIG6L	Write Protection bits (Block 3 code memory area) 1 = Block 3 is not write-protected 0 = Block 3 is write-protected
WRT2	CONFIG6L	Write Protection bits (Block 2 code memory area) 1 = Block 2 is not write-protected 0 = Block 2 is write-protected
WRT1	CONFIG6L	Write Protection bits (Block 1 code memory area) 1 = Block 1 is not write-protected 0 = Block 1 is write-protected
WRT0	CONFIG6L	Write Protection bits (Block 0 code memory area) 1 = Block 0 is not write-protected 0 = Block 0 is write-protected
WRTD	CONFIG6H	Write Protection bit (Data EEPROM) 1 = Data EEPROM is not write-protected 0 = Data EEPROM is write-protected
WRTB	CONFIG6H	Write Protection bit (Boot Block memory area) 1 = Boot Block is not write-protected 0 = Boot Block is write-protected
WRTC	CONFIG6H	Write Protection bit (Configuration registers) 1 = Configuration registers are not write-protected 0 = Configuration registers are write-protected

**Note 1:** Minimum VDD for F devices is 2.3V.

- 2:** When the 3x Multiplier mode is selected, the input frequency has to be 16 MHz. When the 4x Multiplier mode is selected, the input frequency has to be between 8 MHz and 16 MHz.
- 3:** The dedicated In-Circuit Port is available only on the 44-pin TQFP packaged devices. This bit should be programmed to a '0' in all other devices. See [Section 2.2 “Dedicated ICSP/CD Port \(44-Pin TQFP Only\)”](#) for more information.

# PIC18(L)F2X/4XK50

**TABLE 5-3: PIC18(L)F2X/4XK50 BIT DESCRIPTIONS (CONTINUED)**

Bit Name	Configuration Words	Description
EBTR3	CONFIG7L	Table Read Protection bit (Block 3 code memory area) 1 = Block 3 is not protected from table reads executed in other blocks 0 = Block 3 is protected from table reads executed in other blocks
EBTR2	CONFIG7L	Table Read Protection bit (Block 2 code memory area) 1 = Block 2 is not protected from table reads executed in other blocks 0 = Block 2 is protected from table reads executed in other blocks
EBTR1	CONFIG7L	Table Read Protection bit (Block 1 code memory area) 1 = Block 1 is not protected from table reads executed in other blocks 0 = Block 1 is protected from table reads executed in other blocks
EBTR0	CONFIG7L	Table Read Protection bit (Block 0 code memory area) 1 = Block 0 is not protected from table reads executed in other blocks 0 = Block 0 is protected from table reads executed in other blocks
EBTRB	CONFIG7H	Table Read Protection bit (Boot Block memory area) 1 = Boot Block is not protected from table reads executed in other blocks 0 = Boot Block is protected from table reads executed in other blocks
DEV<10:3>	DEVID2	Device ID bits These bits are used with the DEV<2:0> bits in the DEVID1 register to identify part number.
DEV<2:0>	DEVID1	Device ID bits These bits are used with the DEV<10:3> bits in the DEVID2 register to identify part number.
REV<4:0>	DEVID1	Revision ID bits These bits are used to indicate the revision of the device.

**Note 1:** Minimum VDD for F devices is 2.3V.

**2:** When the 3x Multiplier mode is selected, the input frequency has to be 16 MHz. When the 4x Multiplier mode is selected, the input frequency has to be between 8 MHz and 16 MHz.

**3:** The dedicated In-Circuit Port is available only on the 44-pin TQFP packaged devices. This bit should be programmed to a '0' in all other devices. See [Section 2.2 “Dedicated ICSP/CD Port \(44-Pin TQFP Only\)”](#) for more information.

## 5.3 Single-Supply ICSP Programming

The LVP bit in Configuration register, CONFIG4L, enables Single-Supply (Low-Voltage) ICSP Programming. The LVP bit defaults to a '1' (enabled) from the factory.

If Single-Supply Programming mode is not used, the LVP bit can be programmed to a '0'. However, the LVP bit may only be programmed by entering the High-Voltage ICSP mode, where  $\overline{\text{MCLR}}/\text{VPP}/\text{RE3}$  is raised to  $V_{\text{IH}}H$ . Once the LVP bit is programmed to a '0', only the High-Voltage ICSP mode is available and only the High-Voltage ICSP mode can be used to program the device.

**Note 1:** The High-Voltage ICSP mode is always available, regardless of the state of the LVP bit, by applying  $V_{\text{IH}}H$  to the  $\overline{\text{MCLR}}/\text{VPP}/\text{RE3}$  pin.

## 5.4 Embedding Configuration Word Information in the HEX File

To allow portability of code, a programmer is required to read the Configuration Word locations from the hex file. If Configuration Word information is not present in the hex file, then a simple warning message should be issued. Similarly, while saving a hex file, all Configuration Word information must be included. An option to not include the Configuration Word information may be provided. When embedding Configuration Word information in the hex file, it should start at address 300000h.

Microchip Technology Inc. feels strongly that this feature is important for the benefit of the end customer.

## 5.5 Embedding Data EEPROM Information In the HEX File

To allow portability of code, a programmer is required to read the data EEPROM information from the hex file. If data EEPROM information is not present, a simple warning message should be issued. Similarly, when saving a hex file, all data EEPROM information must be included. An option to not include the data EEPROM information may be provided. When embedding data EEPROM information in the hex file, it should start at address F00000h.

Microchip Technology Inc. believes that this feature is important for the benefit of the end customer.

## 5.6 Checksum Computation

The checksum is calculated by summing the following:

- The contents of all code memory locations
- The Configuration Word, appropriately masked
- ID locations (Only if any portion of program memory is code-protected)

The Least Significant 16 bits of this sum are the checksum.

Code protection limits access to program memory by both external programmer (code-protect) and code execution (table read protect). The ID locations, when included in a code-protected checksum, contain the checksum of an unprotected part. The unprotected checksum is distributed: one nibble per ID location. Each nibble is right justified.

Table 5-4 describes how to calculate the checksum for each device.

**Note:** The checksum calculation differs depending on the code-protect setting. Since the code memory locations read out differently depending on the code-protect setting, the table describes how to manipulate the actual code memory values to simulate the values that would be read from a protected device. When calculating a checksum by reading a device, the entire code memory can simply be read and summed. The Configuration Word and ID locations can always be read.

# PIC18(L)F2X/4XK50

**TABLE 5-4: CHECKSUM COMPUTATION**

Device	Code-Protect	Checksum	Blank Value	0xAA at 0 and Max Address <sup>(1)</sup>
PIC18FX4K50 PIC18LFX4K50	None	SUM[0000:07FF]+SUM[0800:1FFF]+SUM[2000:3FFF]+ (CONFIG1L & 3Bh)+ (CONFIG1H & EFh)+(CONFIG2L & 5Fh)+(CONFIG2H & 3Fh)+ (CONFIG3L & 00h)+(CONFIG3H & D3h)+(CONFIG4L & E5h)+ (CONFIG4H & 00h)+(CONFIG5L & 03h)+(CONFIG5H & C0h)+ (CONFIG6L & 03h)+(CONFIG6H & E0h)+(CONFIG7L & 03h)+ (CONFIG7H & 40h)	C404	C35A
	Boot Block	SUM[0800:1FFF]+SUM[2000:3FFF]+ (CONFIG1L & 3Bh)+(CONFIG1H & EFh)+(CONFIG2L & 5Fh)+ (CONFIG2H & 3Fh)+(CONFIG3L & 00h)+(CONFIG3H & D3h)+ (CONFIG4L & E5h)+(CONFIG4H & 00h)+(CONFIG5L & 03h)+ (CONFIG5H & C0h)+(CONFIG6L & 03h)+(CONFIG6H & E0h)+ (CONFIG7L & 03h)+(CONFIG7H & 40h)+SUM_ID	CBD8	CB8D
	Boot/Block 0	SUM[2000:3FFF]+(CONFIG1L & 3Bh)+ (CONFIG1H & EFh)+(CONFIG2L & 5Fh)+(CONFIG2H & 3Fh)+ (CONFIG3L & 00h)+(CONFIG3H & D3h)+(CONFIG4L & E5h)+ (CONFIG4H & 00h)+(CONFIG5L & 03h)+(CONFIG5H & C0h)+ (CONFIG6L & 03h)+(CONFIG6H & E0h)+(CONFIG7L & 03h)+ (CONFIG7H & 40h)+SUM_ID	E3D7	E38C
	All	(CONFIG1L & 3Bh)+(CONFIG1H & EFh)+(CONFIG2L & 5Fh)+ (CONFIG2H & 3Fh)+(CONFIG3L & 00h)+(CONFIG3H & D3h)+ (CONFIG4L & E5h)+(CONFIG4H & 00h)+(CONFIG5L & 03h)+ (CONFIG5H & C0h)+(CONFIG6L & 03h)+(CONFIG6H & E0h)+ (CONFIG7L & 03h)+(CONFIG7H & 40h)+SUM_ID	03D5	03DF

**Legend:** Item                      Description  
 CONFIGx = Configuration Word  
 SUM[a:b] = Sum of locations, a to b inclusive  
 SUM\_ID = Byte-wise sum of lower four bits of all customer ID locations  
 + = Addition  
 & = Bit-wise AND

**Note 1:** 0xAA at address 0 and 0xFF at address 1 for the beginning of program memory; 0xAA at Max address and 0xFF at Max address - 1 for the end of program memory.

# PIC18(L)F2X/4XK50

**TABLE 5-4: CHECKSUM COMPUTATION (CONTINUED)**

Device	Code-Protect	Checksum	Blank Value	0xAA at 0 and Max Address <sup>(1)</sup>
PIC18FX5K50 PIC18LFX5K50	None	SUM[0000:07FF]+SUM[0800:1FFF]+SUM[2000:3FFF]+ SUM[4000:5FFF]+SUM[6000:7FFF]+(CONFIG1L & 3Bh)+ (CONFIG1H & EFh)+(CONFIG2L & 5Fh)+(CONFIG2H & 3Fh)+ (CONFIG3L & 00h)+(CONFIG3H & D3h)+(CONFIG4L & E5h)+ (CONFIG4H & 00h)+(CONFIG5L & 0Fh)+(CONFIG5H & C0h)+ (CONFIG6L & 0Fh)+(CONFIG6H & E0h)+(CONFIG7L & 0Fh)+ (CONFIG7H & 40h)	8428	837E
	Boot Block	SUM[0800:1FFF]+SUM[2000:3FFF]+SUM[4000:5FFF]+SUM[6000:7FFF]+ (CONFIG1L & 3Bh)+(CONFIG1H & EFh)+(CONFIG2L & 5Fh)+ (CONFIG2H & 3Fh)+(CONFIG3L & 00h)+(CONFIG3H & D3h)+ (CONFIG4L & E5h)+(CONFIG4H & 00h)+(CONFIG5L & 0Fh)+ (CONFIG5H & C0h)+(CONFIG6L & 0Fh)+(CONFIG6H & E0h)+ (CONFIG7L & 0Fh)+(CONFIG7H & 40h)+SUM_ID	8BFE	8BB3
	Boot/Block 0/ Block 1	SUM[4000:5FFF]+SUM[6000:7FFF]+(CONFIG1L & 3Bh)+ (CONFIG1H & EFh)+(CONFIG2L & 5Fh)+(CONFIG2H & 3Fh)+ (CONFIG3L & 00h)+(CONFIG3H & D3h)+(CONFIG4L & E5h)+ (CONFIG4H & 00h)+(CONFIG5L & 0Fh)+(CONFIG5H & C0h)+ (CONFIG6L & 0Fh)+(CONFIG6H & E0h)+(CONFIG7L & 0Fh)+ (CONFIG7H & 40h)+SUM_ID	C3FB	C3B0
	All	(CONFIG1L & 3Bh)+(CONFIG1H & EFh)+(CONFIG2L & 5Fh)+ (CONFIG2H & 3Fh)+(CONFIG3L & 00h)+(CONFIG3H & D3h)+ (CONFIG4L & E5h)+(CONFIG4H & 00h)+(CONFIG5L & 0Fh)+ (CONFIG5H & C0h)+(CONFIG6L & 0Fh)+(CONFIG6H & E0h)+ (CONFIG7L & 0Fh)+(CONFIG7H & 40h)+SUM_ID	03EF	03F9

**Legend:** Item      Description  
 CONFIGx = Configuration Word  
 SUM[a:b] = Sum of locations, a to b inclusive  
 SUM\_ID = Byte-wise sum of lower four bits of all customer ID locations  
 + = Addition  
 & = Bit-wise AND

**Note 1:** 0xAA at address 0 and 0xFF at address 1 for the beginning of program memory; 0xAA at Max address and 0xFF at Max address - 1 for the end of program memory.

# PIC18(L)F2X/4XK50

**TABLE 5-4: CHECKSUM COMPUTATION (CONTINUED)**

Device	Code-Protect	Checksum	Blank Value	0xAA at 0 and Max Address <sup>(1)</sup>
PIC18FX6K50 PIC18LFX6K50	None	SUM[0000:07FF]+SUM[0800:3FFF]+SUM[4000:7FFF]+ SUM[8000:BFFF]+SUM[C000:FFFF]+(CONFIG1L & 3Bh)+ (CONFIG1H & EFh)+(CONFIG2L & 5Fh)+(CONFIG2H & 3Fh)+ (CONFIG3L & 00h)+(CONFIG3H & D3h)+(CONFIG4L & E5h)+ (CONFIG4H & 00h)+(CONFIG5L & 0Fh)+(CONFIG5H & C0h)+ (CONFIG6L & 0Fh)+(CONFIG6H & E0h)+(CONFIG7L & 0Fh)+ (CONFIG7H & 40h)	0428	037E
	Boot Block	SUM[0800:3FFF]+SUM[4000:7FFF]+SUM[8000:BFFF]+SUM[C000:FFFF]+ (CONFIG1L & 3Bh)+(CONFIG1H & EFh)+(CONFIG2L & 5Fh)+ (CONFIG2H & 3Fh)+(CONFIG3L & 00h)+(CONFIG3H & D3h)+ (CONFIG4L & E5h)+(CONFIG4H & 00h)+(CONFIG5L & 0Fh)+ (CONFIG5H & C0h)+(CONFIG6L & 0Fh)+(CONFIG6H & E0h)+ (CONFIG7L & 0Fh)+(CONFIG7H & 40h)+SUM_ID	0BF6	0BAB
	Boot/Block 0/ Block 1	SUM[8000:BFFF]+SUM[C000:FFFF]+(CONFIG1L & 3Bh)+ (CONFIG1H & EFh)+(CONFIG2L & 5Fh)+(CONFIG2H & 3Fh)+ (CONFIG3L & 00h)+(CONFIG3H & D3h)+(CONFIG4L & E5h)+ (CONFIG4H & 00h)+(CONFIG5L & 0Fh)+(CONFIG5H & C0h)+ (CONFIG6L & 0Fh)+(CONFIG6H & E0h)+(CONFIG7L & 0Fh)+ (CONFIG7H & 40h)+SUM_ID	83F3	83A8
	All	(CONFIG1L & 3Bh)+(CONFIG1H & EFh)+(CONFIG2L & 5Fh)+ (CONFIG2H & 3Fh)+(CONFIG3L & 00h)+(CONFIG3H & D3h)+ (CONFIG4L & E5h)+(CONFIG4H & 00h)+(CONFIG5L & 0Fh)+ (CONFIG5H & C0h)+(CONFIG6L & 0Fh)+(CONFIG6H & E0h)+ (CONFIG7L & 0Fh)+(CONFIG7H & 40h)+SUM_ID	03E7	03F1

**Legend:** Item      Description  
 CONFIGx = Configuration Word  
 SUM[a:b] = Sum of locations, a to b inclusive  
 SUM\_ID = Byte-wise sum of lower four bits of all customer ID locations  
 + = Addition  
 & = Bit-wise AND

**Note 1:** 0xAA at address 0 and 0xFF at address 1 for the beginning of program memory; 0xAA at Max address and 0xFF at Max address -1 for the end of program memory.

# PIC18(L)F2X/4XK50

## 6.0 AC/DC CHARACTERISTICS TIMING REQUIREMENTS FOR PROGRAM/VERIFY TEST MODE

Standard Operating Conditions						
Operating Temperature: 25°C is recommended						
Param No.	Sym.	Characteristic	Min.	Max.	Units	Conditions
D110	VIHH	High-Voltage Programming Voltage on $\overline{\text{MCLR}}/\text{VPP}/\text{RE3}$	8	9	V	
D111	VDD	Supply Voltage (VDDMIN, VDDMAX)	PIC18LF 1.8	3.6	V	
			PIC18F 2.3	5.5	V	
D111A	VPEW	Voltage during Write or Erase Operations	PIC18LF 2.2V	VDDMAX	V	Row Erase/Write
			VDDMIN	VDDMAX		
D111B	VBULK	Voltage during Bulk Erase Operations	2.7	VDDMAX	V	Bulk Erase operations
D112	IPP	Programming Current on $\overline{\text{MCLR}}/\text{VPP}/\text{RE3}$	—	300	μA	
D113	IDDP	Supply Current During Programming	—	10	mA	
D031	VIL	Input Low Voltage	VSS	0.2 VDD	V	
D041	VIH	Input High Voltage	0.8 VDD	VDD	V	
D080	VOL	Output Low Voltage	—	0.6	V	IO <sub>L</sub> = 8.5 mA @ 3.0V
D090	VOH	Output High Voltage	VDD – 0.7	—	V	IO <sub>H</sub> = 3.0 mA @ 3.0V
D012	CIO	Capacitive Loading on I/O pin (PGD)	—	50	pF	To meet AC specifications
P1	TR	$\overline{\text{MCLR}}/\text{VPP}/\text{RE3}$ Rise Time to enter Program/Verify mode	—	1.0	μs	(Note 1)
P2	TPGC	Serial Clock (PGC) Period	100	—	ns	VDD = 3.6V
			1	—	μs	VDD = 1.8V
P2A	TPGCL	Serial Clock (PGC) Low Time	40	—	ns	VDD = 3.6V
			400	—	ns	VDD = 1.8V
P2B	TPGCH	Serial Clock (PGC) High Time	40	—	ns	VDD = 3.6V
			400	—	ns	VDD = 1.8V
P3	TSET1	Input Data Setup Time to Serial Clock ↓	15	—	ns	
P4	THLD1	Input Data Hold Time from PGC ↓	15	—	ns	
P5	TDLY1	Delay between 4-bit Command and Command Operand	40	—	ns	
P5A	TDLY1A	Delay between 4-bit Command Operand and next 4-bit Command	40	—	ns	
P6	TDLY2	Delay between Last PGC ↓ of Command Byte to First PGC ↑ of Read of Data Word	20	—	ns	
P9	TDLY5	PGC High Time (minimum programming time)	1	—	ms	Externally Timed
P9A	TDLY5A	PGC High Time	5	—	ms	Configuration Word programming time
P10	TDLY6	PGC Low Time after Programming (high-voltage discharge time)	200	—	μs	
P11	TDLY7	Delay to allow Self-Timed Bulk Erase to occur	PIC18(L)FX5K50 15	—	ms	
			PIC18(L)FX6K50			
			PIC18(L)F24K50	12	—	ms
P11A	TDRWT	Data Write Polling Time	4	—	ms	

**Note 1:** Do not allow excess time when transitioning  $\overline{\text{MCLR}}$  between VIL and VIHH; this can cause spurious program executions to occur. The maximum transition time is:  
 $1 \text{ T}_{\text{CY}} + \text{TPWRT}$  (if enabled) + 1024 TOSC (for LP, HS, HS/PLL and XT modes only) + 2 ms (for HS/PLL mode only) + 1.5 μs (for EC mode only) where T<sub>CY</sub> is the instruction cycle time, TPWRT is the Power-up Timer period and TOSC is the oscillator period. For specific values, refer to the Electrical Characteristics section of the device data sheet for the particular device.

# PIC18(L)F2X/4XK50

## 6.0 AC/DC CHARACTERISTICS TIMING REQUIREMENTS FOR PROGRAM/VERIFY TEST MODE (CONTINUED)

Standard Operating Conditions						
Operating Temperature: 25°C is recommended						
Param No.	Sym.	Characteristic	Min.	Max.	Units	Conditions
P11B	TDLY7B	Delay for Self-Timed Memory Write	2	—	ms	
P12	THLD2	Input Data Hold Time from $\overline{\text{MCLR}}/\text{VPP}/\text{RE3} \uparrow$	2	—	$\mu\text{s}$	
P13	TSET2	$\text{VDD} \uparrow$ Setup Time to $\overline{\text{MCLR}}/\text{VPP}/\text{RE3} \uparrow$	100	—	ns	
P14	TVALID	Data Out Valid from $\text{PGC} \uparrow$	10	—	ns	
P15	THLD4	Input data hold time from $\overline{\text{MCLR}} \uparrow$	400	—	$\mu\text{s}$	
P16	TDLY8	Delay between Last $\text{PGC} \downarrow$ and $\overline{\text{MCLR}}/\text{VPP}/\text{RE3} \downarrow$	0	—	s	
P17	THLD3	$\overline{\text{MCLR}}/\text{VPP}/\text{RE3} \downarrow$ to $\text{VDD} \downarrow$	—	100	ns	
P18	TKEY1	Delay from First $\overline{\text{MCLR}} \downarrow$ to first $\text{PGC} \uparrow$ for Key Sequence on PGD	1	—	ms	
P19	THIZ	Delay from $\text{PGC} \uparrow$ to PGD High-Z	3	10	ns	
P20	TKEY2	Delay from Last $\text{PGC} \downarrow$ for Key Sequence on PGD to Second $\overline{\text{MCLR}} \uparrow$	40	—	ns	

**Note 1:** Do not allow excess time when transitioning  $\overline{\text{MCLR}}$  between  $\text{VIL}$  and  $\text{VIHH}$ ; this can cause spurious program executions to occur. The maximum transition time is:  
 $1 \text{ Tcy} + \text{TPWRT}$  (if enabled) + 1024  $\text{TOSC}$  (for LP, HS, HS/PLL and XT modes only) + 2 ms (for HS/PLL mode only) + 1.5  $\mu\text{s}$  (for EC mode only) where  $\text{Tcy}$  is the instruction cycle time,  $\text{TPWRT}$  is the Power-up Timer period and  $\text{TOSC}$  is the oscillator period. For specific values, refer to the Electrical Characteristics section of the device data sheet for the particular device.



## APPENDIX A: REVISION HISTORY

### Revision A (06/2012)

Initial release of this document.

### Revision B (08/2012)

- Inserted Note 1 and updated the values in the “Blank Value” and “0xAA at 0 and Max Address” columns of [Table 5-4](#).

# PIC18(L)F2X/4XK50

---

NOTES:

---

**Note the following details of the code protection feature on Microchip devices:**

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as “unbreakable.”

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

---

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

**Trademarks**

The Microchip name and logo, the Microchip logo, dsPIC, KEELOQ, KEELOQ logo, MPLAB, PIC, PICmicro, PICSTART, PIC<sup>32</sup> logo, rPIC and UNI/O are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

FilterLab, Hampshire, HI-TECH C, Linear Active Thermistor, MXDEV, MXLAB, SEEVAL and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Analog-for-the-Digital Age, Application Maestro, BodyCom, chipKIT, chipKIT logo, CodeGuard, dsPICDEM, dsPICDEM.net, dsPICworks, dsSPEAK, ECAN, ECONOMONITOR, FanSense, HI-TIDE, In-Circuit Serial Programming, ICSP, Mindi, MiWi, MPASM, MPLAB Certified logo, MPLIB, MPLINK, mTouch, Omniscient Code Generation, PICC, PICC-18, PICDEM, PICDEM.net, PICKIT, PICTail, REAL ICE, rLAB, Select Mode, Total Endurance, TSHARC, UniWinDriver, WiperLock and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2012, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

 Printed on recycled paper.

ISBN: 978-1-62076-511-1

**QUALITY MANAGEMENT SYSTEM**  
**CERTIFIED BY DNV**  
**== ISO/TS 16949 ==**

*Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC<sup>®</sup> MCUs and dsPIC<sup>®</sup> DSCs, KEELOQ<sup>®</sup> code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.*



# MICROCHIP

## Worldwide Sales and Service

### AMERICAS

**Corporate Office**  
2355 West Chandler Blvd.  
Chandler, AZ 85224-6199  
Tel: 480-792-7200  
Fax: 480-792-7277  
Technical Support:  
<http://www.microchip.com/support>  
Web Address:  
[www.microchip.com](http://www.microchip.com)

**Atlanta**  
Duluth, GA  
Tel: 678-957-9614  
Fax: 678-957-1455

**Boston**  
Westborough, MA  
Tel: 774-760-0087  
Fax: 774-760-0088

**Chicago**  
Itasca, IL  
Tel: 630-285-0071  
Fax: 630-285-0075

**Cleveland**  
Independence, OH  
Tel: 216-447-0464  
Fax: 216-447-0643

**Dallas**  
Addison, TX  
Tel: 972-818-7423  
Fax: 972-818-2924

**Detroit**  
Farmington Hills, MI  
Tel: 248-538-2250  
Fax: 248-538-2260

**Indianapolis**  
Noblesville, IN  
Tel: 317-773-8323  
Fax: 317-773-5453

**Los Angeles**  
Mission Viejo, CA  
Tel: 949-462-9523  
Fax: 949-462-9608

**Santa Clara**  
Santa Clara, CA  
Tel: 408-961-6444  
Fax: 408-961-6445

**Toronto**  
Mississauga, Ontario,  
Canada  
Tel: 905-673-0699  
Fax: 905-673-6509

### ASIA/PACIFIC

**Asia Pacific Office**  
Suites 3707-14, 37th Floor  
Tower 6, The Gateway  
Harbour City, Kowloon  
Hong Kong  
Tel: 852-2401-1200  
Fax: 852-2401-3431

**Australia - Sydney**  
Tel: 61-2-9868-6733  
Fax: 61-2-9868-6755

**China - Beijing**  
Tel: 86-10-8569-7000  
Fax: 86-10-8528-2104

**China - Chengdu**  
Tel: 86-28-8665-5511  
Fax: 86-28-8665-7889

**China - Chongqing**  
Tel: 86-23-8980-9588  
Fax: 86-23-8980-9500

**China - Hangzhou**  
Tel: 86-571-2819-3187  
Fax: 86-571-2819-3189

**China - Hong Kong SAR**  
Tel: 852-2401-1200  
Fax: 852-2401-3431

**China - Nanjing**  
Tel: 86-25-8473-2460  
Fax: 86-25-8473-2470

**China - Qingdao**  
Tel: 86-532-8502-7355  
Fax: 86-532-8502-7205

**China - Shanghai**  
Tel: 86-21-5407-5533  
Fax: 86-21-5407-5066

**China - Shenyang**  
Tel: 86-24-2334-2829  
Fax: 86-24-2334-2393

**China - Shenzhen**  
Tel: 86-755-8203-2660  
Fax: 86-755-8203-1760

**China - Wuhan**  
Tel: 86-27-5980-5300  
Fax: 86-27-5980-5118

**China - Xian**  
Tel: 86-29-8833-7252  
Fax: 86-29-8833-7256

**China - Xiamen**  
Tel: 86-592-2388138  
Fax: 86-592-2388130

**China - Zhuhai**  
Tel: 86-756-3210040  
Fax: 86-756-3210049

### ASIA/PACIFIC

**India - Bangalore**  
Tel: 91-80-3090-4444  
Fax: 91-80-3090-4123

**India - New Delhi**  
Tel: 91-11-4160-8631  
Fax: 91-11-4160-8632

**India - Pune**  
Tel: 91-20-2566-1512  
Fax: 91-20-2566-1513

**Japan - Osaka**  
Tel: 81-66-152-7160  
Fax: 81-66-152-9310

**Japan - Yokohama**  
Tel: 81-45-471-6166  
Fax: 81-45-471-6122

**Korea - Daegu**  
Tel: 82-53-744-4301  
Fax: 82-53-744-4302

**Korea - Seoul**  
Tel: 82-2-554-7200  
Fax: 82-2-558-5932 or  
82-2-558-5934

**Malaysia - Kuala Lumpur**  
Tel: 60-3-6201-9857  
Fax: 60-3-6201-9859

**Malaysia - Penang**  
Tel: 60-4-227-8870  
Fax: 60-4-227-4068

**Philippines - Manila**  
Tel: 63-2-634-9065  
Fax: 63-2-634-9069

**Singapore**  
Tel: 65-6334-8870  
Fax: 65-6334-8850

**Taiwan - Hsin Chu**  
Tel: 886-3-5778-366  
Fax: 886-3-5770-955

**Taiwan - Kaohsiung**  
Tel: 886-7-536-4818  
Fax: 886-7-330-9305

**Taiwan - Taipei**  
Tel: 886-2-2500-6610  
Fax: 886-2-2508-0102

**Thailand - Bangkok**  
Tel: 66-2-694-1351  
Fax: 66-2-694-1350

### EUROPE

**Austria - Wels**  
Tel: 43-7242-2244-39  
Fax: 43-7242-2244-393

**Denmark - Copenhagen**  
Tel: 45-4450-2828  
Fax: 45-4485-2829

**France - Paris**  
Tel: 33-1-69-53-63-20  
Fax: 33-1-69-30-90-79

**Germany - Munich**  
Tel: 49-89-627-144-0  
Fax: 49-89-627-144-44

**Italy - Milan**  
Tel: 39-0331-742611  
Fax: 39-0331-466781

**Netherlands - Drunen**  
Tel: 31-416-690399  
Fax: 31-416-690340

**Spain - Madrid**  
Tel: 34-91-708-08-90  
Fax: 34-91-708-08-91

**UK - Wokingham**  
Tel: 44-118-921-5869  
Fax: 44-118-921-5820

11/29/11